Hall Ticket No:											Question Paper Code: 20CE11
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 GEOTECHNICAL ENGINEERING

(Civil Engineering)

Time: 3Hrs

Max Marks: 60

Q. N		Marks	СО	BL	
Q.1	i. Which test is suitable for the field problem where there is a chance of sudden drawdown (that occurs in earth dam or canal embankment)	1M	1	1	
	ii. What do you mean by Liquid Limit	1M	1	1	
	iii. Write the relationship between void ratio and porosity	1M	2	1	
	iv Define Residual Soils	1M	2	2	
	v. Write short note on organic soils	1M	3	1	
	vi Write the difference between the consolidation and compaction	1M	3	2	
	vii. If instead of single drainage, the number of drainage faces is increased to two in corresponding soils, the rate of consolidation will be	1M	4	1	
	viii. Which of the expression is used to calculate the value of earth pressure for active condition (Ka)?	1M	4	1	
	ix. What do you mean by factor of safety	1M	5	1	
	x. Explain the concept of Mohr – Coulomb Failure	1M	5	2	
Q.2(A)	 (i) Differentiate between 'residual' and 'transported' soils. (ii) What do you mean by Liquid Limit, (iii) Define shrinkage limit, (iv) Write the major type of soils found in India? (v) write formula for Plastic index OR	10M	1	2	
Q.2(B)	A sample of saturated soil has a water content of 35%. The specific gravity of solids is 2.65. Determine its void ratio, porosity, saturated unit weight and dry unit weight.	10M	1	4	
Q.3(A)	Compute the total, effective and pore pressure at a depth of 15 m below the bottom of a lake 6 m deep. The bottom of the lake consists of soft clay with a thickness of more than 15 m. The average water content of the clay is 40% and the specific gravity of soils may be assumed to be	10 M	2	4	
	2.65. OR				
Q.3(B)	The discharge of water collected from a constant head permeameter in a period of 15 minutes is 500 ml. The internal diameter of the permeameter is 5 cm and the measured difference in head between two gauging points 15 cm vertically apart is 40 cm. Calculate the coefficient of permeability. If the dry weight of the 15 cm long sample is 4.86 N and the specific gravity of the solids is 2.65, calculate the seepage velocity.	10M	2	4	
Q.4(A)	What is the mechanism of compaction and explain the factors affecting compaction OR	10M	3	3	
Q.4(B)	(i) Explain the Mohr-Coulomb strength envelope (ii) Explain the principle of the direct shear test. What are the advantages of this test?	5M 5M	3	4	
Q.5(A)	A cylindrical specimen of a saturated soil fails under an axial stress $150 \mathrm{kN/m^2}$ in an unconfined compression test. The failure plane makes an angle of 52° with the horizontal. Calculate the cohesion and angle of internal friction of the soil.	10M	4	3	

Q.5(B)	(i) What are the assumptions made in Terzaghi's One dimensional consolidation.	5M	4	4
	(ii) In a consolidation test the following results have been obtained when the load was changed from $50 \mathrm{kN/m^2}$ to $100 \mathrm{kN/m^2}$, the void ratio changed from 0.70 to 0.65. Determine the coefficient of volume decrease mv and the compression index Cc.	5M	4	4
Q.6(A)	How to find the bearing capacity of soil in field and explain any two methods in-detail	10 M	5	4
	OR			
Q.6(B)	In your opinion which is the best to equation among (Terzaghi and IS) evaluate the beating capacity of soil and explain why. *** END***	10M	5	4

Hall Ticket No: Question Paper Code: 2	0CE112
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 TRANSPORTATION ENGINEERING

(Civil Engineering)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	СО	BL
Q.1	i. What is medians?	1M	2	1
	ii. What is pavement unevenness?	1 M	2	1
	iii. What is the basic requirement of a highway alignment?	1 M	1	1
	iv Classify types of roads?	1M	1	1
	v. Define terms speed and density?	1M	3	2
	vi What are the various types of intersection?	1M	4	1
	vii. Explain channelization?	1M	4	2
	viii. What is aggregate crushing test?	1M	4	1
	ix. Explain penetration and ductility test on bitumen?	1 M	4	2
	x. What is full form of AASHTO?	1M	5	1
Q.2(A)	Discuss the objectives of highway planning? What are different types of	10M	1	2
	classification of road? Explain the methods of classification of roads.			
	OR			
	What are the salient features of cross-section of a Highway Alignment?	10M	1	3
Q.2(B)	How do you carried out the engineering surveys for deciding Highway			
	Alignment?			
Q.3(A)	Calculate the SSD on a level road stretch for design speed of 80 kmph	10M	2	4
	for (a) two-way traffic on a two lane road (b) two way traffic on a single			
	lane road? Assume coefficient of friction as 0.37 and reaction time of			
	driver as 2.5 seconds.			
	OR			
Q.3(B)	Define superelevation? why superelevation is important in geometric	10M	2	5
C(-)	design of road?	10111	2	O
Q.4(A)	Explain in detail the various types of signals?	10M	3	2
	OR			
Q.4(B)	Discuss about the Principles of highway lighting.	10M	3	3
Q.5(A)	Discuss Barrier Free concept in Public Transportation. What are the	10M	4	3
. ,	various Barrier Free elements of Public transport,		,	
	OR			
O E/D\		1034	4	_
Q.5(B)	What are the Importance of collective transportation and individual transportation.	10M	4	5
Q.6(A)	Discuss in detail the Role of harbors and ports in transportation.	10M	5	2
	OR			
Q.6(B)	What are the different type of urban transit system?	10M	5	2

Hall Ticket No:						Question Paper Code: 20CE113

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025

DESIGN OF STEEL STRUCTURES

(Civil Engineering)

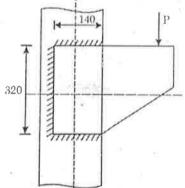
Time: 3Hrs

Max Marks: 60

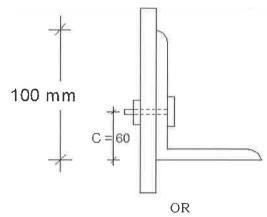
Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q. No		Question	Marks	CO	BL
Q.1	i.	Write any two advantages and disadvantages of bolted connection over welded connection.	1M	1	1
	ii.	What is the relationship between size of weld and throat thickness?	1M	1	2
	iii.	Define the shear lag effect.	1M	2	1
	iv	Define laterally supported beam and laterally unsupported beam.	1M	2	1
	- v.	Differentiate between the column and strut?	1M	3	1
	vi	Define and Classification of built-up compression member.	1 M	3	2
	vii.	What are the failure modes occurred in the plate girder?	1M	4	2
	viii.	In which situation the plate girder is most suitable instead of rolled steel section.	1 M	4	2
	ix.	What are the forces acting on gantry girder?	1M	5	2
	x.	Write the deflection limits of gantry girder when it is carrying vertical loads as per IS 800: 2007	1 M	5	2
Q.2(A)	(i) To 4.6.	determine the design shear capacity of 24 mm diameter bolt of grade	4M	1	5
	(ii) E	xplain the advantages and disadvantages of steel structures.	6M	1	2
		OR			
Q.2(B)	belov	rmine the maximum load that can be resisted by the bracket shown w by fillet weld of size 8 mm, if its workshop welding. Load is acting column face at distance of 250 mm. Take strength of weld is 410 MPa.	10M	1	5



Q.3(A) Determine the tensile strength of a tie member ISA 100 x 75 x 6 mm, 10M 2 5 connected to a gusset plate using 4 bolts of M16, take pitch as 60mm and edge distance as 40mm as shown in below Figure. Also assume material properties fy = 250 N/mm², fu=410 N/mm², and E=2x10⁵ N/mm².



to a dead load of 6 kN/m and live load of 20 kN/m. Assume the beam as fully lateral restraint & stiff bearing support of 100 mm, and fy = 250 N/mm², fu=410 N/mm², and E=2x10 ⁵ N/mm². Q.4(A) Design a column support an axial service load of 450 kN. The column has an effective length of 7 m with respect to z axis and 4.5 m with respect to the y axis. Also assume fy = 250 N/mm², fu=410 N/mm², and E=2x10 ⁵ N/mm². OR Q.4(B) Determine the design axial load on the column section ISMB 350, given that the height of the column is 3.0 m and that it is pin ended. Also assume the following fy = 250 N/mm², fu=410 N/mm², and E=2x10 ⁵ N/mm². Q.5(A) Design a welded plate girder of span 25 m to carry an imposed load of 35 kN/m. Avoid to use bearing and intermediate stiffeners. Assume the material properties as follows: fy = 250 N/mm², fu=410 N/mm², and E=2x10 ⁵ N/mm². OR Q.5(B) (i) Write the design procedure for the design of welded plate girder as per IS 800: 2007. (ii) Explain the design of shear buckling resistance as per IS 800: 2007. Q.6(A) (i) Write the impact load on gantry girder. OR Q.6(B) Design a hand operated travelling crane simply supported by gantry girder for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley = 200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.					
an effective length of 7 m with respect to z axis and 4.5 m with respect to the y axis. Also assume fy = 250 N/mm², fu=410 N/mm², and E=2x105 N/mm². OR Q.4(B) Determine the design axial load on the column section ISMB 350, given that the height of the column is 3.0 m and that it is pin ended. Also assume the following fy = 250 N/mm², fu=410 N/mm², and E=2x105 N/mm². Q.5(A) Design a welded plate girder of span 25 m to carry an imposed load of 35 10M 4 KN/m. Avoid to use bearing and intermediate stiffeners. Assume the material properties as follows: fy = 250 N/mm², fu=410 N/mm², and E=2x105 N/mm². OR Q.5(B) (i) Write the design procedure for the design of welded plate girder as per IS 5M 4 2 800: 2007. (ii) Explain the design of shear buckling resistance as per IS 800: 2007. 4M 4 2 Q.6(A) (i) Write the impact load on gantry girder. OR Q.6(B) Design a hand operated travelling crane simply supported by gantry girder for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley = 200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.	Q.3(B)	to a dead load of 6 kN/m and live load of 20 kN/m. Assume the beam as fully lateral restraint & stiff bearing support of 100 mm, and fy = 250	10M	2	5
Q.4(B) Determine the design axial load on the column section ISMB 350, given that the height of the column is 3.0 m and that it is pin ended. Also assume the following fy = 250 N/mm², fu=410 N/mm², and E=2x105 N/mm². Q.5(A) Design a welded plate girder of span 25 m to carry an imposed load of 35 kN/m. Avoid to use bearing and intermediate stiffeners. Assume the material properties as follows: fy = 250 N/mm², fu=410 N/mm², and E=2x105 N/mm². OR Q.5(B) (i) Write the design procedure for the design of welded plate girder as per IS 5M 4 2 800: 2007. (ii) Explain the design of shear buckling resistance as per IS 800: 2007. 4M 4 2 Q.6(A) (i) Write the impact load on gantry girder. OR Q.6(B) Design a hand operated travelling crane simply supported by gantry girder for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.	Q.4(A)	an effective length of 7 m with respect to z axis and 4.5 m with respect to the y axis. Also assume fy = 250 N/mm^2 , fu= 410 N/mm^2 , and E= $2x10^5 \text{ N/mm}^2$.	10M	3	5
kN/m. Avoid to use bearing and intermediate stiffeners. Assume the material properties as follows: fy = 250 N/mm², fu=410 N/mm², and E=2x10 ⁵ N/mm². OR Q.5(B) (i) Write the design procedure for the design of welded plate girder as per IS 5M 4 2 800: 2007. (ii) Explain the design of shear buckling resistance as per IS 800: 2007. 4M 4 2 Q.6(A) (i) Write the impact load on gantry girder. 4M 5 2 (ii) Explain step by step procedure to design gantry girder. 6M 5 2 OR Q.6(B) Design a hand operated travelling crane simply supported by gantry girder for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley =200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.	Q.4(B)	Determine the design axial load on the column section ISMB 350, given that the height of the column is 3.0 m and that it is pin ended. Also assume	10M	3	5
Q.5(B) (i) Write the design procedure for the design of welded plate girder as per IS 5M 4 2 800: 2007. (ii) Explain the design of shear buckling resistance as per IS 800: 2007. 4M 4 2 Q.6(A) (i) Write the impact load on gantry girder. (ii) Explain step by step procedure to design gantry girder. OR Q.6(B) Design a hand operated travelling crane simply supported by gantry girder for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley =200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.	Q.5(A)	kN/m. Avoid to use bearing and intermediate stiffeners. Assume the material properties as follows: fy = 250 N/mm^2 , fu= 410 N/mm^2 , and E= $2x10^5 \text{ N/mm}^2$.	10M	4	5
800: 2007. (ii) Explain the design of shear buckling resistance as per IS 800: 2007. 4M 4 2 Q.6(A) (i) Write the impact load on gantry girder. (ii) Explain step by step procedure to design gantry girder. OR Q.6(B) Design a hand operated travelling crane simply supported by gantry girder for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley = 200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.					
Q.6(A) (i) Write the impact load on gantry girder. (ii) Explain step by step procedure to design gantry girder. OR Q.6(B) Design a hand operated travelling crane simply supported by gantry girder for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley =200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.	Q.5(B)		5M	4	2
(ii) Explain step by step procedure to design gantry girder. OR Q.6(B) Design a hand operated travelling crane simply supported by gantry girder for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley =200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.		(ii) Explain the design of shear buckling resistance as per IS 800: 2007.	4M	4	2
Q.6(B) Design a hand operated travelling crane simply supported by gantry girder 10M 5 for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley =200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.	Q.6(A)	(i) Write the impact load on gantry girder.	4M	5	2
Q.6(B) Design a hand operated travelling crane simply supported by gantry girder 10M 5 for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley = 200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for buckling and deflections not required.		(ii) Explain step by step procedure to design gantry girder.	6M	5	2
*** END***	Q.6(B)	Design a hand operated travelling crane simply supported by gantry girder for given data. Span of gantry girder = 5 m, span of crane girder = 15 m, Crane capacity = 200 kN, Self-weight of crane girder excluding trolley =200 kN, Self-weight of trolley = 30 kN, Minimum hook approach = 1 m, Distance between wheels = 3.5 m c/c, Self-weight of rails = 0.3 kN/m. check for	10M	5	5

Hall Ticket No:								Question Paper Code: 20EEE112
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(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 **MEASUREMENTS AND TRANSDUCERS**

(EEE)

Time: 3Hrs Max Marks: 60

Q.N	lo Question	Marks	СО	BL
Q.1	 Differentiate between the spring control and gravity control. 	1M	1	1
	 List the different essential torques in indicating instruments. 	1M	1	1
	iii. What is creeping in energy meters?	1M	2	1
	iv Draw the LPF wattmeter circuit symbol.	1M	2	1
	v. What is standardization in DC potentiometers?	1M	3	1
	vi Give the expression for balancing condition of Wien's bridge.	1M	3	1
	vii. Define DSO and DPO.	1M	4	1
	viii. What are the applications of digital frequency Meter?	1M	4	1
	ix. List the application of strain gauge.	1M	5	1
	x. Define active transducers.	1M	5	1
Q.2(A)	With a neat diagram explain in detail the construction and working of	10M	1	2
	PMMC instrument.			
(-)	OR			
Q.2(B)	A moving-coil ammeter has a fixed shunt of 0.02 Ω . With a coil resistance of	10M	1	3
	R = 1000 Ω and a potential difference of 500 mV across it. Full-scale			
	deflection is obtained. (a) To what shunted current does it correspond? (b)			
	Calculate the value of R to give full-scale deflection when shunted current I			
	is 10 A.			
Q.3(A)	Explain the double element and three-element wattmeter and drive the equations.	10M	2	2
	OR			
Q.3(B)	Explain the single-phase induction type energy meter with proper sketch.	10M	2	2
Q.4(A)	With a neat diagram explain in detail the construction and working of a	10M	3	3
	Polar type AC potentiometer.			
	OR			
Q.4(B)	With a neat diagram explain the loss of charge method.	10M	3	3
Q.5(A)	Explain Digital storage oscilloscope with relevant block Diagram.	10M	4	3
	OR			
Q.5(B)	Explain Q-meter with relevant block Diagram.	10M	4	3
Q.6(A)	Define Transducer, explain the principle and working of Inductive type transducer.	10M	5	3
	OR			
Q.6(B)	Explain Strain gauge and its working with neat sketch.	10M	5	2
	ii) Explain Photo Diode with diagram.		-	-
	*** END***			

Hall Ticket No:						Question Paper Code: 20EEE113

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 SIGNALS & SYSTEMS

(EEE)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

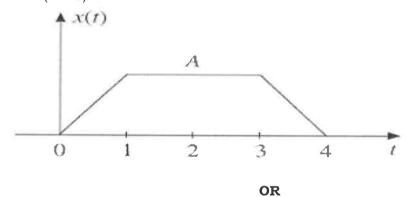
All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.N	Го	Question	Marks	CO	BL
Q.1	i.	Define system.	1 M	1	1
	ii.	State causal system.	1 M	1	2
	iii.	Write the expression for $y_p(t)$ if input is $x(t) = e^{at} u(t)$	1M	2	1
	iv	Define Transfer Function.	1M	2	2
	V.	Write expression for calculating the trigonometric Fourier series coefficient a_n	1M	3	1
	vi	State frequency convolution theorem.	1 M	3	1
	vii.	Define Bilateral Laplace transform.	1M	4	2
	viii.	Find the initial value of the following function $X(s) = \frac{s+4}{s^2+3s+5}$	1 M	4	1
	ix.	State Sampling.	1M	5	1
	x.	Define Nyquist rate in sampling.	1M	5	2
Q.2(A)	For t	the given x(t) sketch the following	10M	1	3

i. x(-3t+2)

ii. x(t+2)

iii. x(-3t+3)



Q.2(B) Determine whether the following signal is power signal or energy signal. 10M 1 3 Also find the energy and power of the signal

$$x(n) = \begin{cases} n^2 & 0 \le n \le 4 \\ 10 - n & 5 \le n \le 10 \\ 0 & \text{Otherwise} \end{cases}$$

Q.3(A)	Determine the convolution of the following two sequences.	10M	2	3
	$x(n) = \{1,4,3,2\}$ and $h(n) = \{1,3,2,1\}$			
	OR			
Q.3(B)	For a Given system represented by difference function	10M	2	3
	y(n) + y(n-1) - 6y(n-2) = x(n) with initial conditions $y(-1) = 3$, $y(-2) = 0$,			
	find the response due to input $x(n) = 2^n u(n)$.			

Q.4(A)	Find the Fourier transform of the following signals.	10M	3	3
	$a. x(t) = e^{-t} \sin 5t \ u(t)$			
	b. $x(t) = e^{-3t} \cos 6t u(t)$			
	OR			
Q.4(B)	Find the 5-point DFT of the following sequence.	10M	3	2
	$x(n) = \{1, -2, 3, 4, 2\}$			
Q.5(A)	a). Explain any three properties of Laplace transform with proofs.	10M	4	3
	b). Explain the properties of ROC in Laplace transform. OR			
Q.5(B)	Find the Z-Transform and ROC of X(Z) for	10M	4	2
	$x(n) = 3\left(\frac{5}{7}\right)^n u(n) + 2\left(-\frac{1}{3}\right)^n u(n)$ also plot the ROC diagram.			
Q.6(A)	Explain any two of the sampling techniques.	10M	5	2
	OR			
Q.6(B)	Determine the Nyquist sampling rate and Nyquist sampling interval for the following.	10M	5	3
	a. $x(t) = 2sinc(100\pi t)$			
	b. $x(t) = \frac{1}{2} sinc(100\pi t) + \frac{1}{2} sinc(50\pi t)$			
	c. $x(t) = sinc(100\pi t) + 3sinc^2(60\pi t)$ *** END***			

Hall Ticket No: Question Paper Code: 208
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(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025

POWER SYSTEMS-II

(EEE)

Time: 3Hrs

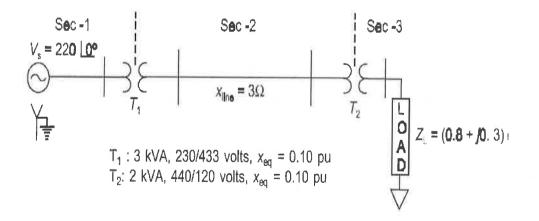
Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

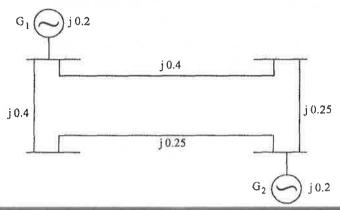
Q.N	lo	Question	Marks	CO	BL
Q.1	i.	Define: Primitive network.	1M	1	1
	II.	Write the advantages of Per Unit system.	1M	1	1
	III.	In load flow studies, the PV bus is treated as PQ bus whenlimit is violated.	1M	2	1
	iv	State the advantages of Newton Raphson method of load flow solution.	1M	2	1
	٧.	What are the methods for calculation of Zbus matrix.	1M	3	1
	vi	State the expression for short circuit MVA for symmetrical fault analysis.	1M	3	1
	vii.	Write down the relation between original unbalanced vector and the corresponding symmetrical components of a three-phase system.	1M	4	1
	viii	Draw the phasor diagram of negative sequence three phase voltages of sequence component for unbalanced phasors.	1M	4	1
	ix.	Write the expression for Critical clearing time.	1M	5	1
	х.	Classify the power system stability.	1M	5	1
Q.2(A)	For t	he given power system, draw the per unit impedance diagram and	10M	1	3

Q.2(A) For the given power system, draw the per unit impedance diagram and also evaluate the per unit impedances and per unit source voltage at the base of 3 kVA and 230 V.



OR

Form the YBus by using Singular transformation for the network shown 10M 3 in figure including generator buses.



Explain clearly the computational procedure for load flow solution using Q.3(A) Gauss-Seidel method when the power system contains all types of buses.

10M

3

2

OR

Derive the Power Flow Equations in load flow studies. Q.3(B)

10M

2 3

Derive an expression for the modified Zbus matrix when a link added Q.4(A) between two old buses.

10M

3

3

OR

Obtain the Bus Impedance Matrix for the network configuration Q.4(B) displayed in the table (Bus 0 is the reference bus) by Zbus building algorithm.

10M

3 3

Line code (From Bus to To Bus)	Reactance (pu)
1-2	j0.25
1-4	j0.2
2-3	j0.1
2-4	j0.4
3-4	j0.25
0-1	j0.2
0-2	j0.25

Q.5(A)Derive the expression for sequence component of current and voltages in L-L-G fault with fault impedance.

10M

3

OR

Derive the expression for symmetrical components of voltage and Q.5(B) currents from unbalanced vectors.

10M 3 4

Q.6(A) Discuss briefly the methods to improve the stability.

10M

10M

3

3

5

Q.6(B) Discuss the methods of improving stability of the power system network.

Hall Ticket No:			Question Paper Code: 20ME112
MADANAPAL	LE INSTITUTE	OF TECHNOLOGY	& SCIENCE, MADANAPALLE

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 CAD/CAM

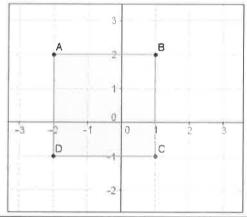
(Mechanical Engineering)

Time: 3Hrs

Q.2(B)

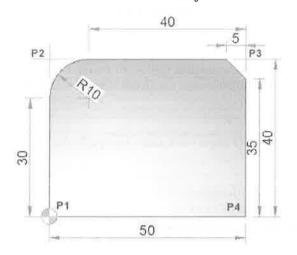
Max Marks: 60

Q.No	Question	Marks	СО	BL
Q.1	i. What is the need of CAD data exchange format?	1	1	1
	ii. What is rasterization?	1	1	1
	iii. What are the basic requirement to generate a plane surface?	1	2	1
	iv What is the significance of synthetic curves in CAD/CAM?	1	2	1
	v. List the different types of tool magazine.	1	3	1
	vi What is transducer?	1	3	1
	vii. The miscellaneous function code M30 is used for which purpose in part programming?	1	4	1
	viii. Explain a typical block of word address format using a suitable example.	1	4	1
	ix. What is the need of flexible manufacturing system in industries?	1	5	1
	x. What was the foundation of the Second Industrial Revolution?	1	5	1
Q.2(A)	Write a short note on the following CAD data exchange format: IGES ACIS DXF STL file	10	1	2
	OR			
	Translate the below figure (i) 3 units to the right and 4 units down.	10	1	3



Q.3(A)	Explain constructive solid geometry technique? Also, elaborate their advantages and limitations.	10	2	2
	OR			
Q.3(B)	Explain different analytical and synthetic curve entities of geometric modelling.	10	2	3
Q.4(A)	What is numeric control system? Elaborate the different components of numeric control system.	10	3	3

Q.4(B	Explain different types of CNC machining centers.	10	3	3	
Q.5(A	Write a complete CNC part program to machine the given geometry as sho	10	4	3	
	in Figure Assume suitable data if necessary. All dimensions are in mm				



OR

Q.5(B)	Describe the various steps involved in the development of a part program,	10	4	3
Q.6(A)	Write a short notes on Big data and data mining The Internet of Things Horizontal and Vertical system integration Simulation	10	5	2
Q.6(B)	OR Explain group technology with a suitable example. Also, elaborate its advantages and limitations. *** END***	10	5	3

Hall Ticket No:										Question Paper Code: 20ME113
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025

AUTOMATION & ROBOTICS

(Mechanical Engineering)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	СО	BL
Q.1	i. What is the use of a hopper in an automation system?	1M	1	1
	ii. What are the different types of automation?	1M	1	1
	iii. Define ideal cycle time.	1M	2	1
	iv. Define balance efficiency.	1M	2	1
	v. List out various robot configurations.	1M	3	1
	vi Define D.O.F.	1M	3	1
	vii. What is the main goal of trajectory planning in robotics?	1M	4	1
	viii. Why is straight-line motion preferred in certain robotic applications?	1M	4	1
	ix. What does SCARA stand for, and what is its primary application?	1 M	5	1
	What does SCARA stand for, and what is its primary application?			
	x. What is the primary function of a manipulator arm in an industrial	1M	5	1
	robot?			
Q.2(A)	Explain the need for automation. Describe the level of automation.	10M	1	2
	OR			
Q.2(B)	Describe hardware components for automation and name three reasons for	10M	1	2
,	including a storage buffer in an automated production line	10111	_	
Q.3(A)	A 20-station transfer line is divided into two stages of 10 stations each. The	10M	2	3
- 、 /	ideal cycle time of each stage is $T_c = 10$ min. All of the stations in the line	10111		0
	have the same probability of stopping, p = 0.005. We assume that the			
	downtime is constant when a breakdown occurs, $T_d = 8.0$ min. Using the			
	upper-bound approach, compute the line efficiency for the following buffer			
	capacities (a) $b = 0$ and (b) $b = \infty$			
	OR			
Q.3(B)	What is the importance of line balancing? Explain any two methods of line	10M	2	2
	balancing.			
Q.4(A)	Describe Inverse kinematics with suitable examples.	10M	3	2
	OR			
Q.4(B)	Discuss the performance characteristics of actuators. Compare electrical,	10M	3	3
£, (=)	and pneumatic actuators based on their characteristics.	10101	5	3
Q.5(A)		10M	4	2
2.0(.1)	Describe Newton-Euler formulation	10171	4	2
0.5(D)	OR			
Q.5(B)	Explain the different ways of accomplishing lead through the method of	10M	4	4
	robot programming.			
Q.6(A)	Describe various types of sensors used in the robot	10M	5	2
	or			
Q.6(B)	Describe the major components of an industrial robot.	10M	5	2
- , ,	V 1	2011	~	~

Hall Ticket No:						Question Paper Code: 20ME114
					1 1	-

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025
MACHINE LEARNING FOR MECHANICAL ENGINEERS

(Mechanical Engineering)

Time: 3Hrs

Max Marks: 60

Q.No	Question		Marks	СО	BL
Q.1	 Why is machine learning important 	nt?	1 M	1	2
	ii. What are the 3 ways to measure co	entral tendency?	1M	1	1
	iii. Is regression supervised learning?	Why?	1 M	2	2
	iv. Distinguish between classification		1 M	2	2
	Why is the odd value of "K" preferr	red over even values in the KNN	1 1 7	2	0
	Algorithm?		1 M	3	2
	vi Can the KNN algorithm be used for	r regression problem	1 M	3	2
	statements?		1 1/1	3	3
	vii. Why is it necessary to perform cros	ss validation?	1 M	4	2
	viii. Define support vectors		1M	4	1
	ix. What is deploy a machine learning		1 M	5	1
	x. Name different clouds used in Mac	chine Learning.	1M	5	1
Q.2(A)	Explain the Supervised Learning approa	ch with an example.	1074	_	_
Q.2(A)			10M	1	2
		OR			
Q.2(B)	Calculate the following for	the given dataset:			
C ()	9,17,24,38,5,26,42,18,33,24	givon databot.	10M	1	3
	Mean (ii) Median (iii) Mode (iv) Standard	Deviation (v) Variance	1011	1	J
Q.3(A)	The following data on the drying time of				
2.0(11)	of an additive that is intended to reduce				
	scatter plot to verify that it is reas				
	relationship is parabolic b) Fit a second				
	method of least square c) using the resu				
	the varnish when 6.5 grams of the additi				
	the variash when 0.5 grams of the additi	ive is being used.			
	Amount of varnish additive (grams) X	Drying time (hours) Y			
	0	12	10M	2	3
	1	10.5			_
	2	10			
	3	8			
	4	7			
	5	8			
	6	7.5			
	7	8.5			
		9			
	8	9			
).3(B)		OR			

Q.4(A)	The following data related to CNC lathe turning operation. Predict the)
	surface roughness value for (200, 0.13) using k-NN algorithm, take	
	k = 3.	

Cutting Speed (m/min)	Feed (mm/rev)	Surface Roughness (µm)
100	0.15	0.58
185	0.10	0.49
140	0.14	0.50
108	0.11	0.45
172	0.12	0.69
180	0.09	0.78
190	0.19	0.35
155	0.17	0.62
200	0.13	55

OR

Q.4(B)	Suppose that the data mining task is to cluster points (with (x,y)
	representing location) into three clusters, where the points are A1(4,11),
	A2(2,6), A3(8,5), B1(7,9), B2(7,4), B3(5,3), C1(2,4), C2(4,9). The distance
	function is Euclidean distance. Suppose initially we assign A1, B1, and
8:	C1 as the center of each cluster, respectively. Use the k-means
	algorithm to show only

10M 3 3

10M

3

3

a. The three cluster centers after the first round of execution.

b. The final three clusters.

Q.5(A)	Explain how support vector machine solves linear classification problems.	10M	4	2
	OR			
Q.5(B)	Describe the different kernel functions used in SVM.	10M	4	2
Q.6(A)	Explain 3 ways to deploy Machine Learning models in cloud.	10M	5	2
	OR			
Q.6(B)	Which tools have you used to deploy a machine learning model? Explain any one in detail	10M	5	2

Hall Ticket No: Question Paper Code: 20HU

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 UNIVERSAL HUMAN VALUES

(Common to All)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	CO	BL
Q.1	i. Mention the basic guidelines for value education	1 M	1	1
	ii. Define Happiness.	1 M	1	3
	iii. Outcome of self-regulation is	1 M	2	2
	iv What are the needs of the self and how they are full-filled?	1 M	2	1
	v. People living with differing goals are called as	1 M	3	2
	vi Is feeling of relationship natural acceptable to you or feeling of opposition natural acceptable to you?	1M	3	1
	vii. Write the four orders in nature.	1M	4	2
	viii Write the inheritance of Bio-order.	1M	4	2
	ix. Entry point for Human Tradition (in which Human Goal is fulfilled generation after generation) is?	1M	5	1
	x. Ethical Human Conduct of a Professional implies?	1M	5	3
Q.2(A)	Explain the process of self-exploration. What is the expected result of self-exploration? Please explain the process, content and natural outcome of self-exploration with a neat diagram and two examples of your life. OR	10M	1	3
Q.2(B)	Discuss the programme for continuity in happiness.	10M	1	2
Q.3(A)	What is qualitative difference between the activities of the self and those of the body? Illustrate with few examples. OR	10M	2	3
Q.3(B)	What purpose does physical facility serve for a human being? Explain categorically.	10M	2	1
Q.4(A)	Respect is right evaluation (on the basis of the self). Write some of the prevailing notions regarding the feeling of respect. examine these notions as well as the proposal for the feeling of respect. OR	10M	3	3
Q.4(B)	Listed the dimensions (systems) that comprised a human order. Explain how each dimension contributes to the fulfillment of the human goal.	10M	3	2
Q.5(A)	List four orders in nature with the examples of units in each order. What is the basis of this classification?	10M	4	3
	OR			
Q.5 (B)	Existence is all that exists. What are the two types of realities that exist? Explain how you can distinguish these realities.	10M	4	2
Q.6 (A)	In Spite of the increasing number and stringency of measures to curb corruption, this malaise is ever growing. Explain the reason for this situation.	10M	5	4
	OR			
Q.6 (B)	Explain the implications of value-based living.	10M	5	3

Hall Ticket No:						Question Paper Code: 20ECE111

(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 VLSI Design

(ECE)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.N	o Question	Marks	СО	BL
Q.1	i. List out the applications of MOSFET.	1M	1	1
	ii. Draw a CMOS inverter.	1M	1	1
	iii. List the advantages and disadvantages of domino logic.	1M	2	1
	iv Define the dynamic power dissipation?	1M	2	1
	v. Draw a true single phase latch circuit.	1M	3	1
	vi Define the pipelining?	1M	3	1
	vii. Draw a 1-bit DRAM cell.	1M	4	1
	viii. What are the operations of funnel shifter.	1M	4	1
	ix. List the advantages of FPGA	1M	5	1
	x. What is meant by IDDQ test?	1M	5	1
Q.2(A)	Derive the drain current expression for n channel MOSFET with neat	10M	1	3
	sketches.			
	OR			
Q.2(B)	Discuss in detail about Pass Transistor Logic and Transmission gate and	10M	1	2
	implement 2:1 Multiplexer using Transmission gate.			
Q.3(A)	Explain in detail about sources of power dissipation of CMOS gate	10M	2	2
	OR			
Q.3(B)	Design of 4:1 multiplexer using pass transistor logic.	10M	2	4
Q.4(A)	Illustrate the operation of Sense-Amplifier Based Registers with circuit	10M	3	2
	operation.			
	OR			
Q.4(B)	Discuss the operation of dynamic edge triggered register using transmission gate.	10M	3	2
0.5/4)		4004		
Q.5(A)	Design a 4*4 Barrel shifter with examples.	10M	4	2
	OR			
Q.5(B)	Design a 16-bit carry select adder with neat sketches.	10M	4	2
Q.6(A)	Explain in detail about boundary scan technique.	10M	5	2
	OR			
Q.6(B)	Describe FPGA Building block architecture with suitable diagram.	10M	5	2
	*** END***			

Hall Ticket No: Question Paper Code: 2
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(UGC-AUTONOMOUS)

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 ANTENNA AND MICROWAVE ENGINEERING

(ECE)

Time: 3Hrs

Max Marks: 60

	Marks	CO	\mathbf{BL}
i. Define radiation pattern of an antenna?	1M	1	1
	e 1M	1	3
	1M	2	1
		2	2
v. What are the major bands available in microwave frequencies?	1 M	3	1
vi List the applications of microwave frequencies.	1 M	3	2
vii. What is the principle of Wilkinson power divider?	1 M	4	1
The state of the s	1 M	4	2
Gunn diode?	f 1 M	5	1
x. Differentiate between klystrons and TWT?	1 M	5	2
Briefly discuss the following: i. Radiation Intensity ii. Beam Efficiency iii. Directivity iv. Radiation Resistance	10M	1	2
OR			
The normalized radiation intensity of an antenna is represented by $E(\theta) = Cos^2 2\theta$ for $0^{\circ} \le \theta \le 90^{\circ}$, $0^{\circ} \le \theta \le 360^{\circ}$. Find the following: i. HPBW (Degrees and Radians) ii. FNBW (Degrees and Radians)	10M	1	4
Illustrate the radiation mechanisms of broad side antenna array and	10M	2	2
·			
	101/	0	0
	TOM	2	2
Explain in detail the applications of Microwave engineering based on communications and non-communication utilities.	10M	3	2
Illustrate the concept of microwave radiation. How does microwave radiation affects human body.	10M	3	3
How do you use the E and H Plane Tee? Describe the E and H plane and locate the S-matrix.	10M	4	2
OR Derive the expression for S matrix of a Wilkinson power divider using even-odd mode analysis.	10M	4	3
Describe the Gunn diode in detail, using the schematic and the V-I characteristics.	10M	5	2
OR			
Write Short Notes on i) IMPAAT Diode	10M	5	2
	 ii. The radiation resistance of an antenna is 72Ω and loss resistance is 8 Ω. What is the directivity (in dB) if the power gain is 15. iii. What is meant by uniform linear arrays? iv In what ways does the End Fire Array Pattern need to be achieved? v. What are the major bands available in microwave frequencies? vi. List the applications of microwave frequencies. vii. What is the principle of Wilkinson power divider? viii. Which material is used in Gunn diode and draw the symbol of Gunn diode? x. Differentiate between Butterworth and Chebyshev low pass filter? ix. Which material is used in Gunn diode and draw the symbol of Gunn diode? x. Differentiate between klystrons and TWT? Briefly discuss the following: i. Radiation Intensity ii. Beam Efficiency iii. Directivity iv. Radiation Resistance OR The normalized radiation intensity of an antenna is represented by E (θ) = Cos²2θ for 0° ≤ 0 ≤ 90°, 0° ≤ 0 ≤ 360°. Find the following: i. HPBW (Degrees and Radians) Illustrate the radiation mechanisms of broad side antenna array and end fire antenna array with neat sketches. OR What is understood by uniform linear array of antenna? Derive an expression for array factor of N element uniform linear array. Explain in detail the applications of Microwave engineering based on communications and non-communication utilities. OR Illustrate the concept of microwave radiation. How does microwave radiation affects human body. How do you use the E and H Plane Tee? Describe the E and H plane and locate the S-matrix. OR Derive the expression for S matrix of a Wilkinson power divider using even-odd mode analysis. Describe the Gunn diode in detail, using the schematic and the V-I characteristics.	ii. The radiation resistance of an antenna is 72Ω and loss resistance is 8 Ω. What is the directivity (in dB) if the power gain is 15. iii. 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FNBW (Degrees and Radians) Illustrate the radiation mechanisms of broad side antenna array and end fire antenna array with neat sketches. OR What is understood by uniform linear array of antenna? Derive an expression for array factor of N element uniform linear array. Explain in detail the applications of Microwave engineering based on communications and non-communication utilities. OR Illustrate the concept of microwave radiation. How does microwave radiation affects human body. How do you use the E and H Plane Tee? Describe the E and H plane and locate the S-matrix. OR Derive the expression for S matrix of a Wilkinson power divider using even-odd mode analysis. Describe the Gunn diode in detail, using the schematic and the V-I characteristics.	ii. The radiation resistance of an antenna is 72Ω and loss resistance is 8 Ω. What is the directivity (in dB) if the power gain is 15. iii. What is meant by uniform linear arrays? iv In what ways does the End Fire Array Pattern need to be achieved? v. What are the major bands available in microwave frequencies? v. What are the major bands available in microwave frequencies? v. What is the applications of microwave frequencies. vii. What is the principle of Wilkinson power divider? viii. Differentiate between Butterworth and Chebyshev low pass filter? ix. Which material is used in Gunn diode and draw the symbol of Gunn diode? x. Differentiate between klystrons and TWT? Briefly discuss the following: i. Radiation Intensity ii. Beam Efficiency iii. Directivity iv. Radiation Resistance OR The normalized radiation intensity of an antenna is represented by ii. HPBW (Degrees and Radians) ii. FNBW (Degrees and Radians) iii. FNBW (Degrees and Radians) iii. FNBW (Degrees and Radians) Illustrate the radiation mechanisms of broad side antenna array and end fire antenna array with neat sketches. OR What is understood by uniform linear array of antenna? Derive an expression for array factor of N element uniform linear array. Explain in detail the applications of Microwave engineering based on communications and non-communication utilities. OR Illustrate the concept of microwave radiation. How does microwave radiation affects human body. How do you use the E and H Plane Tee? Describe the E and H plane and load even-odd mode analysis. Describe the Gunn diode in detail, using the schematic and the V-I 10M 5 characteristics. OR

Hall Ticket No: Question Paper Code: 20EC	E113
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(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 DIGITAL COMMUNICATION

(ECE)

Time: 3Hrs Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q. N	lo Question	Marks	со	BL								
Q.1	i. List out various types of distortions available in Delta Modulation.	1M	1	1								
	ii. What is Quantization?	1M	1	1								
	iii. Design the unipolar RZ code for the binary data 101101.	1M	2	6								
	iv What is a Matcher filter?	1M	2	1								
	v. Distinguish between bandwidth requirement of FSK and QPSK. 1M 3											
	vi What is the necessity of constellation diagram? 1M 3											
	vii. Recall the statement of Shannon-Hartley theorem.	1M	4	1								
	viii. Define Error function (erf).	1M	4	1								
	ix. What is eye diagram?	1M	5	1								
	x. Outline the need for carrier synchronization. 1M 5											
Q.2(A)	Explain the types of quantization used in PCM and Drive an expression	10M	1	2								
	for output SNR of a uniform quantizer.											
	OR											
Q.2(B)	Explain about Time Division Multiplexing with neat sketches. 10M 1 2											
Q.3(A)												
	expression for its impulse response.											
	OR											
Q.3(B)	Design various encoding schemes for the data 101001110	10M	2	6								
Q.4(A)	Analyze the working of 8-QAM modulation and demodulation with neat	10M	3	4								
	sketches.											
4 1	OR											
Q.4(B)	Explain the generation and detection of binary PSK.	10M	3	2								
Q.5(A)	Determine the expression for Probability of Error of an ASK system.	10M	4	4								
	OR											
Q.5(B)	Determine the expression for Probability of Error of a QPSK system.	10M	4	4								
Q.6(A)	Explain the effect of frequency offset on received symbols with the help	10M	5	2								
	of constellation diagram.											
	OR											
Q.6(B)	Outline in detail about the PLL based carrier recovery with neat	10M	5	2								
	sketches.											

Hall Ticket No:						Question Paper Code: 18ECE115

(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 COMPUTER COMMUNICATION NETWORKS

(ECE - Re-admitted)

Time: 3Hrs

Max Marks: 60

Q.N	No	Question	Marks	СО	BL
Q.1	i.	Match the following to one or more layers of the TCP/IP protocol	1M	1	1
		suite:			
		a. route determination b. connection to transmission media			
		c. providing services for the end user			
	ii.	Name three types of transmission impairment.	1M	1	1
	iii.	Distinguish between communication at the network layer and communication at the data-link layer.	1M	2	2
	iv	How does a single-bit error differ from a burst error?	1M	2	1
	٧.	Find the class of the following classful IP addresses:	1M	2	3
		a. 130.34.54.12 b. 200.34.2.1 c. 245.34.2.8	400		_
	vi	A host is sending 100 datagrams to another host. If the identification number of the first datagram is 1024, what is the	1M	2	2
		identification number of the last?			
	vii.	Can you explain why some transport-layer packets may be received	1M	4	2
	viii.	out of order in the Internet? UDP is a message-oriented protocol. TCP is a byte-oriented	1M	4	2
	V 1114	protocol. If an application needs to protect the boundaries of its	TIVI	4	2
		message, which protocol should be used, UDP or TCP?			
	ix.	In FTP, can a server get the list of the files or directories from the client?	1M	5	2
	х.	Can a host use a TELNET client to get services provided by other	1M	5	2
	~~	client-server applications such as FTP or HTTP?	7141	J	2
Q.2(A)	a. Gi	ve a detailed description of TCP/IP protocol suit.	10M	1	3
	b. As	ssume a system uses five protocol layers. If the application program			
		tes a message of 100 bytes and each layer (including the fifth and the			
		adds a header of 10 bytes to the data unit, what is the efficiency (the			
	syste	of application layer bytes to the number of bytes transmitted) of the em?			
	,	OR -			
		ompare and contrast a circuit-switched network and a packet- ched network.	10M	1	3
Q.2(B)		ined network. light signal is travelling through a fiber. What is the delay in the signal			
Q.2(D)	if the	length of the fiber-optic cable is 10 m, 100 m, and 1 Km (assume a agation speed of 2×10^8 m)?			
	prop	abation speed of 2 ^ 10 mj;			

Q.3(A)	 a. Discuss in detail about the HDLC frame format. What are the different HDLC frames. Draw their frame formats. b. Byte-stuff the following frame payload in which E is the escape byte, F is the flag byte, and D is a data byte other than an escape or a flag character 											
	DEDDFDEEDFD											
	OR											
Q.3(B)	a. Write a short on the following.i. ALOHA	10M	2	2								
	ii. CSMA/CA											
	iii. CSMA/CD											
0.4/^\	Evaluin in detail about	10M	3									
Q.4(A)	Explain in detail about i. Link State Routing	TOIVI	5	2								
	ii. Border Gateway Protocol											
	OR											
(-)				_								
Q.4(B)	i. Describe Internet Protocol version 4 in detail.	10M	4	3								
	ii. Show the n leftmost bits of the following network-											
	addresses/masks that can be used in a forwarding table a) 170.40.11.0/24 b) 110.40.240.0/22 c) 70.14.0.0./18											
0.5/4\		4004										
Q.5(A)	i. Explain the services of transmission control protocol.	10M	4	2								
	ii. b. Explain the deadlock condition created by lost											
	acknowledgment? OR											
Q.5(B)	i. Differentiate between connectionless and connection-oriented	10M	4	2								
	protocols.											
	ii. b. How congestion windows is used to control the congestion in TCP?											
Q.6(A)	Briefly explain about	10M	5	2								
	i. Secure shell											
	ii. Domain Name System											
	OR											
Q.6(B)	Write a short note on	10M	5	2								
	i. Simple Network Management Protocol.											
	ii. File Transfer Protocol.											

Hall Ticket No:						Question Paper Code: 20CSE11
						Question raper code. 20CSETT

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 COMPILER DESIGN

(Computer Science & Engineering)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	СО	BL
Q.1	i. What are the functions of compiler?	1 M	1	1
	ii. Define boot strapping.	1 M	1	1
	iii. Define ambiguous grammar.	1M	2	1
	iv Eliminate left factoring from the below grammar.	1M	2	2
	S→ iBtS iBtSeS a			
	$B \rightarrow b$			
	v. Define synthesized attribute and inherited attribute.	1 M	3	1
	vi List the rules for type checking.	1M	3	1
	vii. List the Intermediate code representation.	1M	4	1
	viii, Define symbol table.	1 M	4	1
	ix. What is the dead code elimination?	1 M	5	1
	x. Define Peephole optimization.	1 M	5	1
Q.2(A)	Discuss about various phases of a compiler and write down the output of	10M	1	3
	each phase for the expression x:=a+b+c*100 (a,b and c are float variables).			
	OR			
O O(D)	What is LEX? Discuss the usage of LEX in lexical analyser generation with an	10 M	1	2
Q.2(B)	example.	10 111	_	_
Q.3(A)	Explain the following with suitable example	10M	2	2
2.0(1.1)	a) Left Recursive b) Left Factoring	10101	4	
	OR			
).3(B)	Construct the LL(1) parser for the following grammar:	101/	0	_
(تر)ی.	S \rightarrow (L) / a	10M	2	3
	$L \rightarrow L$, S/S. and parse the input string (a,a).			
) 4(A)		1074	*	0
Q.4(A)	Construct SLR Parser for the following grammar: E->E+T T	10M	2	3
	T->T*F F			
	F-> (E) id			
	OR			
O 4/D)				
Q.4(B)	Construct CLR parsing table for the following grammar:	10M	3	3
	$S \to CC$			
	$C \rightarrow cC / d$			
Q.5(A)	Draw the syntax tree and DAG for the expression (a*b)+(c-d)*(a*b)+b.	10M	4	3
	OR			
> = (D)				
Q.5(B)	Explain in detail about Runtime storage management with examples	10M	4	2
Q.6(A)	What is Code optimization? Explain in detail about Loop optimization with an	10M	5	
2.0(21)	example.	10101	3	2
	OR OR			
) 6 (D)		1005	_	_
2.6(B)	Sketch the flow graph for the matrix addition program below.	10M	5	3
	begin			
	for $i := 1$ to n do			
	for $j := 1$ to n do			
	c[i,j] := a[i,j] + b[i,j];			
	end *** END***			

Hall Ticket No: Question Paper Code: 2
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 INTERNET OF THINGS

(Computer Science & Engineering)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.1 i. How does the "Small Pieces, Loosely Joined" principle apply to connected devices in IoT? ii. List the key features of IoT. iii. Define Microprocessor. iv Define System-on-Chip (SoC). v. List the various versions of Raspberry pi models. vi Differ Arduino and Raspberry Pi. viii. What is DNS? viii. What is DNS? viii. What is DNS? viii. What is DNS? viii. What is Comet? Q.2(A) Explain briefly about the main components of IoT in detail. OR Q.2(B) Discuss in detail about any five flavors of IoT. OR Q.3(A) Summarize about the key components of the Arduino board. OR Q.3(B) Explain the factors that need to be considered while choosing your platform in IoT. Q.4(A) Explain about the hardware involved in Raspberry Pi. OR Q.4(B) Analyze the role of the Raspberry Pi in enabling Plug Computing and its impact on IoT. Q.5(B) Explain in detail about the HTTP protocol suite with neat sketch. OR Q.5(B) Explain in detail about the HTTP protocol and HTTPs protocol. OR Q.5(B) Explain the role of MQTT Protocol in IoT. OR Q.5(B) Explain the role of MQTT Protocol in IoT. OR Q.5(B) Explain the role of MQTT Protocol in IoT. OR	Q.No	Question	Marks	CO	BL								
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Q.5(B) Explain in detail about the HTTP protocol and HTTPs protocol. 10M 4 Q.6(A) Briefly explain about the implementation of CoAP protocol in IoT. 10M 5 OR	Q.4(B)		10M	3	4								
Q.5(B) Explain in detail about the HTTP protocol and HTTPs protocol. 10M 4 Q.6(A) Briefly explain about the implementation of CoAP protocol in IoT. 10M 5 OR	Q.5(A)	Discuss about TCP/IP protocol suite with neat sketch.	10M	4	2								
Q.6(A) Briefly explain about the implementation of CoAP protocol in IoT. 10M 5 OR		OR											
OR	Q.5(B)	Explain in detail about the HTTP protocol and HTTPs protocol.	10M	4	2								
	Q.6(A)	Briefly explain about the implementation of CoAP protocol in IoT.	10M	5	2								
Q.6(B) Explain the role of MQTT Protocol in IoT. 10M 5		OR											
	Q.6(B)	Explain the role of MQTT Protocol in IoT.	10M	5	2								

Hall Ticket No:						Question Paper Code: 20CSE11

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 SOFTWARE ENGINEERING

(Computer Science & Engineering)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	CO	BL							
Q.1	i. What do you mean by software engineering?	1 M	1	1							
	ii. Mention the Advantage and Disadvantage of waterfall model.	1 M	1	1							
	iii. Differentiate verification and validation.	1 M	2	2							
	Iv List the different activities of requirement Engineering Process.	1 M	2	1							
	v. What are the five types of Design Classes?	1 M	3	1							
	vi What is the need for modularity?	1M	3	1							
	vii. Define Smoke Testing	1M	4	1							
	viii. What is meant by debugging?	1M	4	1							
	ix. Define the cost of quality.	1M	5	1							
	x. What is meant by software reliability?	1M	5	1							
Q.2(A)	10M	1	2								
	OR										
Q.2(B)	Discuss about the different Principles of Agile Software Engineering. 10M 1										
Q.3(A)	What is Software Requirement Specification (SRS)? Explain in Detail. 10M 2 2										
	OR										
Q.3(B)	Explain in detail about Behavioral models with an example.	10M	2	2							
Q.4(A)	Design and Implement the following diagram with an example. a) Class diagram b) Usecase diagram OR	10M	3	2							
Q.4(B)	Explain about the user interface design golden rules.	10M	3	2							
Q.5(A)	Explain in detail about Metrics for the analysis model.	10M	4	2							
	OR										
Q.5(B)	Summarize about the various testing strategies for conventional software.	10M	4	2							
Q.6(A)	Explain in detail about Software Reliability.	10M	5	2							
	OR										
Q.6(B)	Discuss about the ISO 9000 quality standards.	10M	5	2							
	III TAYDAI										

Hall Ticket No:						Question Paper Code: 20CST111
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 CRYPTOGRAPHY AND NETWORK SECURITY

(Computer Science & Technology)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	СО	BL
Q.1	i. What is Avalanche Effect?	1M	1	1
	ii. List out the round function of AES Algorithm.	1 M	1	1
	iii. Find the Euler's Totient Function for the number 77.	1M	2	1
	iv Find the value of 4^{30} mod 31.	1 M	2	1
	v. Why do we need Hashing in authentication.	1 M	3	1
	vi What is sequence and timing modification.	1 M	3	1
	vii. Define E-mail security.	1 M	4	1
	viii. What is the need to follow security practice.	1M	4	1
	ix. Define Masquerader.	1M	5	1
	x. Mention the two countermeasures for security.	1M	5	1
Q.2(A)	Explain AES.	10M	1	2
	OR			
Q.2(B)	Consider the plaintext "CST" to be encrypted using the Hill cipher with a 3x3 key matrix. The key matrix is given as:	10M	1	4
	[3 2 4]			
	Key Matrix: 5 7 8			
	[3 6 1]			
	Perform the encryption process step by step and determine the resulting			
	ciphertext.			
Q.3(A)	Perform the Diffie-Hellman key exchange algorithm with the following	10M	2	4
	parameters:			
	a. Publicly agreed prime number (p): 29			
	b. Publicly agreed primitive root (g): 3			
	c. Alice's private key (a): 7			
	d. Bob's private key (b): 11.			
	OR			
Q.3(B)	Perform the key exchange process step by step, including the calculation	10M	2	4
	of the shared secret key.			
Q.4(A)	Explain about Digital signature and authentication protocols.	10M	3	2
	OR			
Q.4(B)	Explain briefly MAC and HMAC.	10M	3	2
€··(=)		10111		
Q.5(A)	Explain in detail about IP security with corresponding applications.	10M	4	2
	OR			
Q.5(B)	What is Web security explain the steps with full description.	10M	4	2
Q.0(D)	what is web security explain the steps with full description.	TOW	4	2
Q.6(A)	Explain in detail about Nature of viruses and structure of virus with virus	10M	5	2
• •	countermeasures.			_
	OR			
Q.6(B)	Briefly explain the need for firewall and briefly explain the different types	10M	5	2
· · · ·	of firewalls.	7 0141	J	
	*** END***			

Hall Ticket No:	Question Paper Code: 20CST112
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 CLOUD COMPUTING

(Computer Science & Technology)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	СО	BL
Q.1	i. List out the characteristics of cloud computing.	1M	1	1
	ii. List out the risks and challenges associated with cloud	1M	1	1
	computing.			
	iii. Define about public cloud.	1 M	2	1
	iv. Define hybrid cloud & its benefits?	1M	2	1
	v. What is the difference between Type 1 and Type 2 hypervisors?	1 M	3	2
	vi What is a hypervisor?	1 M	3	2
	vii. What is Architectural Styles for Cloud Applications?	1M	4	2
	viii. What is ZooKeeper in cloud computing?	1M	4	2
	ix. Why is security important in cloud computing?	1M	5	1
	x. What is Elastic Compute Cloud (EC2) in Amazon Web Services (AWS)?	1M	5	2
Q.2(A)	Discuss in detail about Advanced cloud architectures.	10M	1	2
	OR			
Q.2(B)	Discuss in detail about fundamental cloud architectures.	10M	1	2
Q.3(A)	Explain types of Cloud Computing.	10M	2	2
	OR			
Q.3(B)	Explain the steps involved in SLA life cycle. How various aspects like	10 M	2	2
	security, data encryption, privacy etc. can be included in SLA?			
Q.4(A)	Define virtualization and explain types of virtualizations.	10M	3	2
	OR			
Q.4(B)	Explain the steps involved in provisioning a virtual machine, from	10M	3	2
	selecting the hardware resources to configuring the software stack.			
Q.5(A)	Explain the concept of workflows and their significance in distributed syst	10M	4	2
	OR			
Q.5(B)	Describe the GrepTheWeb application, its goals, and the challenges it	10M	4	2
£ ()	addresses. Explain how cloud computing principles, such as scalability,	10111		
	fault tolerance, and distributed processing, are utilized in the			
	GrepTheWeb application.			
Q.6(A)	Explain the importance of third-party APIs in cloud development and	10M	5	4
C ()	discuss the challenges and benefits of working with external APIs.	~ ~ 111	J	'
	OR			
Q.6(B)	Discuss the cost models of AWS, Google App Engine, and Microsoft	10M	5	4
C - (-)	Azure. Compare and contrast their pricing structures, including pay-as-	1 0 171	5	'
	you-go, reserved instances, and pricing tiers.			
	*** END***			

Hall Ticket No:											Question Paper Code: 20CST113
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 INTERNET AND WEB PROGRAMMING

(Computer Science & Technology)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	CO	BL
Q.1	i. Define Session and Cookies.	1M	1	1
	ii. What is the use of VPN?	1M	1	1
	iii. Define DNS.	1M	2	2
	iv. Summarize some text formatting tags available in Mark-up	1M	2	1
	languages.			
	v. Discuss the general syntactic characteristics of JavaScript.	1M	3	1
	vi Write a PHP Script using Date and Time Functions.	1 M	3	1
	vii. Compare SGML, HTML & XML	1 M	4	1
	viii. What is PDO?	1M	4	2
	ix. List the threats in internet security.	1 M	5	1
	x. Define XSL and XSLT.	1M	5	1
Q.2(A)	Why is HTTP called as a stateless protocol? Explain.	10M	1	2
	OR			
Q.2(B)	What is webserver? Explain its Functionalities.	10M	1	2
Q.3(A)	Define XML. What are the basic rules to write XML document? Explain	10M	2	2
	with syntax.			
	OR			
Q.3(B)	Describe the basic structure of HTML5. Use necessary code to explain	10M	2	3
	how one can define client side image map in html.			
2.4(A)	Illustrate a PHP program to create a one-dimensional array and	10M	3	3
	associative array.			
	OR			
2.4(B)	Use a java script that reads an integer, determines and displays	10M	3	2
	whether it is odd or even number.			
Q.5(A)	With the help of suitable PHP script explain querying single and	10M	4	2
	multiple MySQL Databases with PHP.			
	OR			
2.5(B)	Outline the commands DDL, DML, DCL with suitable example.	10M	4	3
).6(A)	Examine sockets and services with suitable examples	10M	5	4
	OR			
).6(B)	Analyse how hackers are threat to the internet security illustrate your	10M	5	4
	view on it.			

Hall Ticket No:						Question Paper Code: 20CAI113

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 BIG DATA ANALYTICS

(CSE-Artificial Intelligence)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	СО	BL					
Q.1	i. Compare value and veracity.	1M	1	1					
	ii. Define Crazy Egg tool.	1M	1	1					
	iii. How node manager and resource manager differ? 1M								
	iv. List out the Hadoop IO classes.	1M	2	2					
	v. What is intermediate data?	1M	3	1					
	vi Differentiate between object writable and generic writable.	1M	3	1					
	vii. What is RDD? Why it is needed in Spark?	1 M	4	1					
	viii. How to declare mutable and immutable variables in Scala?	1M	4	1					
	ix. List out the features of Hbase.	1M	5	1					
	x. Define NoSQL and why it is used?	1M	5	1					
Q.2(A)	Compare & contrast small data vs big data.	10M	1	2					
	OR								
Q.2(B)	Q.2(B) Define big data analytics. Give real time applications of big data. 10M 1 2								
Q.3(A)	Explain the architecture of Building blocks of Hadoop.	10M	2	2					
	OR								
Q.3(B)	Define Hadoop IO. Explain the HDFS Write operation.	10M	2	3					
Q.4(A)	Implement MapReduce program to find the wordcount from text file.	10M	3	3					
	OR								
Q.4(B)	2.4(B) Explain in detail about anatomy of a MapReduce job run.								
Q.5(A)	Implement a Scala Program to print 1 to n even numbers using for loop.	10M	4	3					
	OR								
Q.5(B)	Illustrate the built-in control structures with a simple Scala program.	10M	4	4					
Q.6(A)	Explain in detail about the creating, updating and deleting documents using Hbase.	10M	5	2					
	OR								
Q.6(B)	Compare RDBMS and Hbase.	10M	5	2					

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(UGC-AUTONOMOUS)

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 DEEP LEARNING

(CSE-Artificial Intelligence)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	CO	BL
Q.1	i. Compare vector and Tensor Usage in Deep Learning?	1 M	1	2
	ii. How do you identify high bias and High variance?	1M	1	1
	iii. List three types of error metrics used to assess the performance o	f 1M	2	1
	regression model.			
	iv. How are R^2 and adjusted R^2 different?	1 M	2	2
	v. Give the mathematical equation of the logit function.	1 M	3	1
	vi Which activation function is used to address vanishing gradients	3 1M	3	4
	problem and How?			
	vii. Input image size 28 X 28 and a kernel/filter of size 7 X 7 with a	1 M	4	3
	stride of 1. the size of the convoluted matrix is?			
	viii. What is Batch Normalization?	1 M	4	2
	ix. What is the drawback of RNN, how this drawback can be	: 1M	5	4
	addressed.			
	x. Write on Denoising auto encoders?	1M	5	2
Q.2(A)	i) If $f(x_1,x_2) = x_1^2 + 2x_2$, where $x_1 = e^{2t}$ and $x_2 = e^{t2}$. Find the gradient vector	5M	1	3
	with respect to $\frac{\partial f}{\partial t}$.			
		5M		
	ii) If $z = (2x+y^2)^3$. Find $\frac{\partial z}{\partial x}$, $\frac{\partial z}{\partial y}$ by using chain rule.			
	OR			
Q.2(B)	Explain in detail about Gradient Descent with momentum with	10M	1	2
	examples.			
Q.3(A)	Derive the equation of the logit function which is used in Logistic	10M	2	3
	regression?		_	Ü
	OR			
Q.3(B)	Obtain regression equation of Yon X and estimate Y when X=65 from	10M	2	3
	the following:			
	X 20 30 40 50 60			
	Y 38 40 55 60 65			
0.4(4)	******	1015		
Q.4(A)	With neat architectural diagram, explain the topological layers used in		3	5
	Feed forward neural network. Which activation functions are used in			
	each layers and why?			
	OR			
Q.4(B)	Explain the various types of Gradient Decent methods? Which one is	10M	3	4
	mostly preferred while training a Deep Learning model and Why?			
Q.5(A)	Construct pixel values of an output image for the following input and	10M	4	3
, ,	filter values with stride=1 and stride=2.	201,2		J

input =

filter=						
1	0	1				
0	1	0				
1	0	1				

	OR			
Q.5(B)	Why do we need regularization in Deep learning models? Elaborate any	10M	4	5
	three regularization approaches practiced in Deep learning models?			
Q.6(A)	Write on sequence data. Which model is preferred to train on sequence	10M	5	2
	data. Explain the model in brief.			
	OR			
Q.6(B)	Construct the steps involved in how a denoising autoencoder is trained to map a corrupted data point x¹to its original data point x. *** END***	10M	5	6

Hall Ticket No:	Question Paper Code: 20CAI11
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 DATA SCIENCE

(CSE-Artificial Intelligence)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	СО	BL
Q.1	i. How can you explain the importance of Data Science?	1 M	1	2
	ii. Remember and list out the steps involved in Data Science Life cycle.	1 M	1	1
	iii. How do you understand Big-data? Give me any 2 real-time examples.	1 M	2	2
	iv. Define correlation and causation with suitable example.	1M	2	2
	v. What do you mean by Named Tuple? Give an example	1 M	3	1
	vi How will you understand Conditional Probability? Give an example	1 M	3	1
	vii. Define bias and variance	1M	4	1
	viii. Why Dimensionality reduction is important?	1M	4	1
	ix. Differentiate classification and clustering.	1 M	5	2
	x. What is the use of recommender system?	1 M	5	1
Q.2(A)	Explain in detail about the data pre-processing steps in detail.	10M	1	2
OR Q.2(B)	How to deploy the data science project? Explain all the steps from data collection to deploying the model	10M	1	2
Q.3(A)	What is the use of Data Visualization? Can you explain minimum 5 types of charts with suitable code to visualize the data?	10M	2	2
OR Q.3(B)	How to Find the Correlation Coefficient? Calculate the correlation coefficient of the given data and identify the correlation type x 50 51 52 53 54 y 3.1 3.2 3.3 3.4 3.5	10M	2	4
Q.4(A)	List out the Types of distribution functions and explain any 3 in each category	10M	3	3
	OR			
Q.4(B)	Describe the properties of the normal distribution, including its shape, central tendency, and dispersion. Discuss its importance in statistical analysis.	10M	3	3
Q.5(A)	What is MNIST? Exploring Hand-written Digits using SVM.	10M	4	2
Q.5(B)	OR What is Clustering? Explain K-means clustering algorithm with suitable example.	10M	4	2
Q.6(A)	Discuss in detail Recommender Systems through User-based and Itembased filtering models	10M	5	3
	OR			
Q.6(B)	What are two major types of clustering approaches? Illustrate them with suitable example and diagrams	10M	5	2
	*** END***			

Hall Ticket No:		72.5				Question Paper Code: 20CSD114

(UGC-AUTONOMOUS)

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 DEEP LEARNING

(CSE-Data Science)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	CO	BL
Q.1	i. Write the differences between machine learning and deep learning	1M	1	2
	ii. Name one variant of gradient descent used in machine learning. Explain?	1 M	1	2
	iii. What are the different types of classification algorithm?	1 M	2	1
	iv. What is the purpose of the SoftMax cross entropy loss function in classification tasks?	1 M	2	1
	v. What is dropout, and why is it used in neural networks?	1 M	3	2
	vi Name one popular activation function used in neural networks.	1 M	3	1
	vii. What does RCNN stand for, and what problem does it address in object detection?	1 M	4	2
	viii. What problem do Long Short-Term Memory (LSTM) architectures aim to solve?	1 M	4	2
	ix. What distinguishes Recurrent Neural Networks (RNNs) from feed forward neural networks?	1 M	5	2
	x. What aspect of data representation do contractive autoencoders focus on?	1 M	5	1
Q.2(A)	Discuss the importance of optimization algorithms in training machine learning models and compare different variants of gradient descent? OR	10M	1	2
Q.2(B)	Explain the concepts of overfitting and underfitting, and provide strategies to address these issues in machine learning models?	10M	1	4
Q.3(A)	Describe how linear models address regression problems, including the mathematical formulation of linear regression. Discuss the assumptions underlying linear regression and potential limitations of the model? OR	10M	2	2
Q.3(B)	Explain the fundamental difference between regression and classification problems. Provide examples of each type of problem and discuss their applications in real-world scenarios?	10M	2	4
Q.4(A)	How does a multi-layer perceptron differ from a single-layer perceptron in terms of architecture and capabilities?	10M	3	5
Q.4(B)	OR Describe the characteristics and advantages of the hyperbolic tangent (tanh) activation function compared to the sigmoid activation function?	10M	3	2
Q.5(A)	Compare and contrast the architectural differences between VGG and GoogLeNet (Inception), highlighting their respective strengths and Weaknesses?	10M	4	2
Q.5(B)	Explain the concept of pooling in CNNs and its role in reducing spatial dimensions and extracting dominant features from feature maps?	10M	4	4
Q.6(A)	a) What is the advantage of RNNs for processing sequential data?b) Why are word embeddings important in NLP, and how are they generated?	10M	5	2
	OR			
Q.6(B)	How do LSTM architectures differ from traditional RNNs, and how do they address the problem of vanishing gradients in recurrent neural networks?	10M	5	2

Hall Ticket No:						Question Paper Code: 20CSD115

(UGC-AUTONOMOUS)

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 COMPUTER NETWORKS

(CSE-Data Science)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	CO	BL
Q.1	i. Define computer networks	1 M	1	1
	ii. How do you define Data and Signals	1 M	1	1
	iii. Classify the Channelization protocols	1 M	2	1
	iv. Illustrate the Flow Control	1 M	2	1
	v. How do you use ad hoc network?	1 M	3	1
	vi Identify the Differences of IPV4 and IPV6	1 M	3	1
	vii. Select the network performance measurements	1 M	4	1
	viii. List the factors affecting network performance?	1 M	4	1
	ix. Evolutes client Server Programming	1 M	5	1
	x. Explain Client Server Programming	1 M	5	1
Q.2(A)	What is a packet switching in computer networks?	10M	1	2
	OR			
Q.2(B)	What are the seven layers of ISO-OSI model and explain those layers?	10M	1	2
Q.3(A)	Summaries the addressing type used in the link layer?	10M	2	2
	OR			
Q.3(B)	Explain Hamming code and how does it work? Encode a binary word	10M	2	2
	11001 into the even parity hamming code.			
Q.4(A)	How does the distance vector algorithm work?	10M	3	3
	OR			
Q.4(B)	Apply the Congestion control algorithm in networking	10M	3	3
Q.5(A)	Examine the main difference between SCTP and UDP?	10M	· 4	4
	OR			
Q.5(B)	Analyse about flow control?	10M	4	4
Q.6(A)	Classify the main function of the application layer?	10M	5	2
	OR			
Q.6(B)	Explain the applications of client-server architecture?	10M	5	2

Hall Ticket No: Question Paper Code: 20CSO1	Hall Ticket No:												Question Paper Code: 20CSO11
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 BIG DATA ANALYTICS

(CSE-IOT)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	CO	BL
Q.1	i. What is big data?	1M	1	1
	ii. Compare between conventional data and big data.	1M	1	4
	iii. List the types of stores in data stream management system.	1M	2	1
	iv What is a bloom filter?	1 M	2	1
	v. What is speculative execution?	1 M	3	1
	vi What are the mandatory and optional phases of Hadoop MapReduce framework?	1 M	3	1
	vii. What is IBM Big insights?	1M	4	1
	viii. How does Pig handle schema flexibility and evolving data structures?	1M	4	1
	ix. What is Http Request Object?	1M	5	1
	x. What is the use of the property ready State in XMLHttpRequest object?	1 M	5	1
Q.2(A)	(i) What is analysis and reporting? Compare between analysis and reporting.	5M	1	4
	(ii) What is Big Data Platform? Explain its features and challenges OR	5M	1	2
(-)	(i) Discuss any five big data platforms.	5M	1	6
Q.2(B)	(ii) Explain the properties and types of data.	5M	1	2
Q.3(A)	Illustrate in detail about the stream data model.	10M	2	2
	OR			
Q.3(B)	Discuss in details about real time analytics platform,	10M	2	6
Q.4(A)	What is MapReduce? Explain with the java code, various phases of MapReduce.	10M	3	5
	OR			
Q.4(B)	Illustrate in detail the design aspects of HDFS with corresponding java code.	10M	3	2
Q.5(A)	Depict the architecture of Hive and explain the services of Hive in detail.	10M	4	2
	OR			
Q.5(B)	Discuss in detail about HBase data model.	10M	4	5
Q.6(A)	Illustrate the key techniques and challenges in predictive analytics.	10M	5	2
	OR			
Q.6(B)	Explain the concept of simple linear regression and its assumptions.	10M	5	5

Hall Ticket No:											Question Paper Code: 20CSO113
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 EMBEDDED SYSTEMS

(CSE-Internet of Things)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	CO	BL
Q.1	i. List out the applications of Embedded Systems	1M	1	1
	 Compare Von-Neumann and Harvard architecture 	1 M	1	2
	iii, Enumerate the bit addressable SFRs of Intel 8051 Microcontroller.	1M	2	1
	iv What will be the contents of Overflow Flag and Carry Flag after	1M	2	2
	the execution of the following Intel 8051 Microcontroller			
	instructions.			
	MOV A, #F1H			
	ADD A, #D2H			
	v. A band-limited analog signal has frequency component of 12 KHz.	1M	3	2
	What must be the minimum sampling frequency so that all the			
	frequency components can be exactly reconstructed later?			
	vi Mention the advantages of Multiplexed Display System.	1M	3	1
	vii. What is deadlock?	1 M	4	1
	viii. Differentiate between Hard Real Time and Soft Real Time Systems.	1 M	4	2
	ix. Define Context Switching.	1M	5	1
	x. List out the various operating modes of ARM processor.	1 M	5	1
Q.2(A)	Explain the characteristics of an embedded system. Also elaborate the	10M	1	2
	quality attributes of an embedded system.			
	OR			
Q.2(B)	i. Distinguish between RISC and CISC Processors	5M	1	3
	ii. Elaborate the various types of cores in Embedded Systems.	5M	1	2
Q.3(A)	Illustrate the memory organization of Intel 8051 microcontroller.	10 M	2	3
	OR			
Q.3(B)	i, Explain the serial communication module of Intel 8051 microcontroller.	5M	2	2
	Illustrate the steps involved in serial transmission of data.			
	ii. Write an 8051-assembly language program to transmit a message "YES"	5M	2	3
	serially at a baud rate of 9600. Assume one start and one stop bit for a 8-			
	bit character.			
Q.4(A)	Explain the working of a successive approximation type A / D converter	10M	3	2
	with a neat block diagram.			
	OR			
Q.4(B)	Explain in detail about the concepts of Emulator and Debugger.	10M	3	2
Q.5(A)	What is a process? Explain the various states of a process with a neat state	1034	1	
Q.J(A)	transition diagram.	10M	4	2

Q.5(B)	i. Expla	a neat Gantt Chart.	5M	4	2						
	ii, For t	the table data given p	erform scheduling usir	ng RMS algorithm:							
		Process Identity	5M	4	4						
		P1	3	20							
		P2	2	5							
		Р3	2	10							
						_					
Q.6(A)	Draw a	nd explain, the archit	ecture of ARM 32-bit r	nicrocontroller with	10M	5	2				
	neat dia	agram?									
			OR								
Q.6(B)	Explain	Explain the addressing modes of ARM processor with suitable examples. 10M									
			*** END***								

Hall Ticket No: Question Paper Code: 200
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 ENVIRONMENTAL IMPACT ASSESSMENT (OE-II)

(Common to All)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	CO	BL
Q.1	 i. Write the different types of impact induced by any project activities? 	1 M	1	2
	ii, What are the common categories of land use in a map?	1M	1	1
	iii. What is biological environment constitute o?	1 M	2	1
	iv. Write the two steps for Biological Impact Assessment.	1M	2	2
	v. What is the geography limit over which the biological impact assessment should be conducted?	1M	3	2
	vi Define deforestation	1M	3	1
	vii. What are the causes of deforestation?	1M	4	1
	viii. Mention the reasons for deforestation.	1 M	4	2
	ix. How much percent of earth's animal and plant depends in the forest.	1 M	5	2
	x. What is the percentage contribution of tropical rain forest of South America on earth's oxygen?	1 M	5	2
Q.2(A)	Explain EIA and illustrate the example of Land Cleaning Activity (L.C.A) in detail.	10M	1	2
	OR			
Q.2(B)	Explain in detail the salient feature and key elements of EIA process.	10M	1	3
Q.3(A)	Describe the systematic approach for the study of impacts on soil and groundwater.	10M	2	3
	OR			
Q.3(B)	Discuss in detail about the "Assessment of Soil and Ground Water Pollution".	10M	2	3
Q.4(A)	Introduce the concept of assessing the impact on vegetation and wild Life and discuss the general methodology for the assessment of Impacts on biological environment.	10M	3	4
- 4 <i>/</i> -:	OR			
Q.4(B)	Discuss in detail the systematic approach for evaluating biological impacts	10M	3	4
Q.5(A)	Explain and define audit in the context of EIA in detail.	10M	4	4
	OR			
Q.5(B)	Define environmental audit according to ICC and differentiate between financial and environmental audit.	10M	4	4
Q.6(A)	Discuss in detail the Prevention & Control of pollution Act.	10M	5	5
	OR			
Q.6(B)	Discuss in detail the Prevention & Control of pollution Act.	10M	5	5

Hall Ticket No:							Question Paper Code: 20CSE301
	1	1					

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 JAVA PROGRAMMING (OE)

(Common to All)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	CO	BL
Q.1	i. What is polymorphism?	1M	1	1
	ii. List out the java buzzwords.	1M	1	1
	iii. What is the function of the 'Final' keyword?	1M	2	1
	iv. Can nested interfaces be private?	1M	2	2
	v. What is the life cycle of thread in Java scaler?	1M	3	1
	vi Differentiate between built-exception and User defined Exception	1 M	3	2
	vii. What are character stream classes?	1 M	4	1
	viii. What is a vector in java?	1M	4	1
	ix. What is JFrame?	1M	5	1
	x. What is the full form of JDBC? Why is it used?	1M	5	2
Q.2(A)	Describe the need for Object Oriented Programming and its unique	10M	1	2
	advantages			
	OR			
Q.2(B)	Write a program to implement the Fibonacci series using for loop	10M	1	3
	control structure. Also Write its main characteristics of a constructor.			
Q.3(A)	Discuss about Deriving Classes Using extends Keyword with examples.	10M	2	3
	Also write a sample program to represent abstract class.			
	OR			
Q.3(B)	Demonstrate the significance of the CLASSPATH environment variable	10M	2	3
	in creating and using a package in JAVA.			
Q.4(A)	Describe the functioning of nested try blocks and thrown class with an	10M	3	2
	example.			
	OR			
Q.4(B)	With a neat sketch, illustrate the lifecycle of a Thread in JAVA	10M	3	3
0.5(4)				
Q.5(A)	Discuss in detail about BufferedInputStream and BufferedOutputStream	10M	4	2
	with suitable examples.			
0 F(D)	OR	4034		_
Q.5(B)	Illustrate implementation of HashSet in Collection framework.	10M	4	3
Q.6(A)	How does access, update the data with JDBC? Illustrate with an	10M	5	3
- (/	example		_	.,
	OR			
Q.6(B)	Write a JAVA program to create different shapes and fill colors using	10M	5	3
· · ·	Applet.		J	9
	about WATTO details			

Hall Ticket No:						Question Paper Code: 20ECE302

(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 VLSI DESIGN

(OE-II: Common to all branches, except ECE)

Time: 3Hrs Max Marks: 60

Q.N	Jo Question	Marks	со	BL
Q.1	i. Draw a voltage transfer curve of CMOS inverter.	1M	1	2
	ii. Discuss the sources of parasitic delay in CMOS circuits and how	1M	1	4
	they can be mitigated	2111	-	•
	iii. Describe how CVSL improves noise immunity	1M	2	2
	iv Explain dynamic power dissipation	1M	2	2
	v. Implement 2:1 multiplexer using transmission gate.	1M	3	5
	vi What is the primary function of a Schmitt trigger	1M	3	1
	vii. What is the primary advantage of dynamic latches and registers	1M	4	1
	over static ones?			
	viii. What is the primary function of a barrel shifter	1M	4	1
	ix. Compare FPGA and CPLD.	1M	5	4
	x. Explain the features of full custom ASIC.	1M	5	2
Q.2(A)	i) Derive the CMOS inverter DC characteristics and obtain the	5M	1	4
	relationship for output voltage at different region in the transfer		-	·
	characteristics.			
	ii) Draw the circuit diagram of CMOS inverter and explain its operation.	5M	1	2
	OR			
Q.2(B)	Design a layout diagram for CMOS 3-input NAND gate.	10M	1	6
Q.3(A)	What is stick diagram and explain about different symbols used for	10M	2	1
Q.5(/ t)	components in Stick diagram. Draw the stick and layout for a two input	10101	2	1
	CMOS NAND gate.			
	OR			
Q.3(B)	Implement full adder using Transmission gate.	10M	2	3
				-
Q.4(A)	Sketch CMOS logic for $Y = ((A+B)(C+D))'$.	10M	3	4
	OR			
Q.4(B)	i) Discuss the concept of pipelining in digital circuits, its benefits, and its	10M	3	4
	implementation challenges.			
	ii) Compare synchronous design and asynchronous design.		3	4
Q.5(A)	Design a 16-bit carry skip adder with block size of 4	10M	4	6
	OR			
Q.5(B)	Explain the following	10M	4	2
	i) Semi-custom ASIC. li) Full Custom ASIC.			
Q.6(A)	Discuss about FPGA Interconnect Routing Procedures	10M	5	4
	OR			
Q.6(B)	Explain in detail about boundary scan method	10M	5	2
. ,	*** END***			
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Hall Ticket No:					Î						Question Paper Code: 20ECE301
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(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 BIO-MEDICAL ELECTRONICS

(OE-II: Common to all branches, except ECE)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.N	lo Question	Marks	СО	BL
Q.1	i. Define Biomedical Transducer	1M	1	1
	ii. What is the human physiology	1M	1	1
	iii. Define Lead. Name the type of leads used for ECG	1M	2	1
	iv Compare between EMG and EEG.	1M	2	2
	v. Write the mathematical expression for cardiac output.	1M	3	1
	vi What is the purpose of using inhalator in respiration measurement.	1M	3	1
	vii. Why Positron Emitters Commonly used in PET?	1M	4	1
	viii. What is the range of frequency of ultrasound waves?	1M	4	1
	ix. List the various aids used for Handicapped person.	1M	5	1
	x. What are the two types of dialysis.	1M	5	1
Q.2(A)	Describe the transducers used for measurement of dissolved ions and	10M	1	2
	gases.			
Q.2(B)	Explain the transducers used for measurement of linear velocity.	10M	1	2
Q.3(A)	Illustrate the block diagram of an EEG unit and explain the different parts in it.	10M	2	2
	OR			
Q.3(B)	Elaborate the steps for the typical recording setup of EMG and ECG with	10M	2	2
	diagram.			
Q.4(A)	Explain in detail about indirect method of blood pressure measurement.	10M	3	2
	OR			
Q.4(B)	Summarize the different types of methods for measurement of blood	10M	3	2
	flow.			
Q.5(A)	Describe the basic principle & components of Magnetic Resonance	10M	4	2
	Imaging system.			
	OR			
Q.5(B)	List the properties of x-rays and explain various subsystems of x-ray machine.	10M	4	3
Q.6(A)	Explain in detail about various parts of Heat Lung machine.	10M	5	2
	OR			
Q.6(B)	Discuss in detail about the Artificial Kidney.	10M	5	2
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Hall Ticket No:										Question Paper Code: 20EEE302
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(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 INTRODUCTION TO MEMS

(OE-II: Common to all branches, except EEE)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.I	lo Question	Marks	со	BL
Q.1	i. What do you understand by MEMS?	1M	1	2
	ii. What is scaling?	1M	1	1
	iii. Name the different types of pressure sensors.	1M	2	1
	iv Write the principle of parallel plate capacitor.	1M	2	1
	v. Give the name of any two silicon compounds.	1M	3	1
	vi What are different types of micro fabrication process?	1M	3	2
	vii. Write the basic principle of the finite element method.	1M	4	1
	viii. What is a gyroscope?	1M	4	2
	ix. Which is the principal material for fabricating optical MEMS?	1M	5	2
	x. What do you understand by turbulence measurement?	1M	5	2
Q.2(A)	Elaborate the multidisciplinary nature of microsystem Design and Manufacturing process.	10M	1	3
	OR			
Q.2(B)	Explain about various industrial applications of MEMS.	10M	1	2
Q.3(A)	Discuss the typical micro pressure sensor assembly with a necessary diagram and explain its working principle in detail.	10M	2	3
	OR			
Q.3(B)	Explain principle and working of accelerometer type of micro sensor.	10M	2	2
Q.4(A)	Explain about following fabrication methods	10M	3	3
	i) Ion implantation ii) Diffusion.			
	OR			
Q.4(B)	Explain Chemical Vapor Deposition (CVD) and Physical Vapor Deposition (PVD) techniques for thin film deposition.	10M	3	3
Q.5(A)	Explore the key design considerations involved in microsystem development.	10M	4	3
	OR			
Q.5(B)	Explain how a piezoelectric principle can be modelled using simulation.	10M	4	4
Q.6(A)	Explain the design and functionality of optical MEMS devices, highlighting their applications and advantages.	10M	5	4
	OR			
Q.6(B)	Detail the working mechanism of micro-actuators employed for controlling fluid flow in microfluidic systems, discussing their performance and potential applications.	10M	5	4
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Hall Ticket No:											Question Paper Code: 20CHE302
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025

GREEN CHEMISTRY AND CATALYSIS FOR SUSTAINABLE ENVIRONMENT

(OE- Common to All)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	СО	BL
Q.1	i. State any two principles of green chemistry.	1 M	1	1
	ii. Illustrate Anti-Markovnikov's rule?	1 M	1	1
	iii. Differentiate positive and negative catalysts, give examples for each.	1 M	2	1
	iv. Give any two examples of Biocatalyst	1M	2	2
	v. What are supercritical fluids?	1M	3	2
	vi Mention any two adverse effects of volatile organic solvents on humans	1 M	3	2
	vii. Differentiate thermolysis with pyrolysis.	1M	4	1
	viii. In which process biomass was treated with bacteria to produce	1 M	4	1
	Methane.			
	ix. List out any two traditional methods of making nanomaterials.	1M	5	1
	x. Define top-down and bottom-up approached in nanomaterial synthesis.	1 M	5	1
Q.2(A)	Describe any four atom economic rearrangement reactions and calculate the	10M	1	6
	percentage economy for each?			
0.000	OR			
Q.2(B)	Brief out the principles of Green chemistry	10M	1	6
Q.3(A)	Describe the synthesis and applications of High silica zeolites?	10M	2	2
	OR			
Q.3(B)	Write a brief note on ZSM-5? Describe the commercial uses?	10M	2	5
Q.4(A)	Write the applications of ScH ₂ O as reaction solvent.	10M	3	6
	OR			
Q.4(B)	With a neat phase diagram explain ScCO ₂ and discuss the application of ScCO ₂ as	10M	3	6
	reaction solvent?			
Q.5(A)	Elaborate on photochemical and sonochemical syntheses with suitable example.	10M	4	
O 5(D)	OR	101/	4	_
Q.5(B)	Elaborate on photochemical and sonochemical syntheses with suitable example.	10M	4	5
Q.6(A)	Discuss in detail the synthesis of nanomaterials using microwave and	10M	5	5
	reflux methods			
	OR			
Q.6(B)	Discuss in detail the synthesis of nanomaterials using microwave and reflux	10M	5	5
•	methods			_
	desire TOTT states			

Hall Ticket No:						Question Paper Code: 20CST301
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 OPERATING SYSTEMS (OE-II)

(Common to All)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	СО	BL
Q.1	i. What is meant by system call?	1 M	1	1
	ii. Write two Objectives of an Operating System.	1 M	1	1
	iii. What is Semaphores?	1M	2	1
	iv. Define Process synchronization.	1 M	2	1
	v. List out the necessary conditions for a Deadlock situation to arise.	1M	3	2
	vi What is CPU Scheduling?	1 M	3	1
	vii. What is Virtual Memory?	1 M	4	1
	viii. What is demand paging?	1 M	4	1
	ix. Draw the Disk Structure	1 M	5	2
	x. How could protect the file sharing?	1 M	5	2
Q.2(A)	Elaborate the operations and generic structure of Operating System.	10M	1	2
	OR			
Q.2(B)	Explain about the computer system organization in detail.	10M	1	2
Q.3(A)	Discuss any two classic problems of synchronization.	10M	2	2
	OR			
Q.3(B)	Illustrate the process of Inter processCommunication,	10M	2	3
Q.4(A)	Assume the following workload in a system Process Arrival Time Burst Time P1 5 5 P2 4 6 P3 3 7 P4 1 9 P5 2 2 P6 6 3	10M	3	3
	Draw a Gantt chart illustrating the execution of these jobs using Round robin scheduling algorithm and also Calculate the average waiting time and average turnaround time. OR			
Q.4(B)	Write about deadlock avoidance algorithm in detail.	10M	3	2
Q.5(A)	Explain the various deadlock handling mechanism in detail.	10M	4	2
	OR			
Q.5(B)	Consider the following memory partitions of 100 KB, 500 KB, 200 KB, 300 KB, and 600 KB. How would each of the First fit Best-Fit and Worst-Fit algorithms place processes of 212 KB, 417 KB, 112 KB, and 426 KB? Rank the algorithms in terms of how efficiently they use memory.	10M	4	3
Q.6(A)	Illustrate the process of any two disk scheduling algorithms.	10M	5	3
	OR			
Q.6(B)	Discuss in detail about different file access methods.	10M	5	2

Hall Ticket No: Question Pa	per Code: 20EEE301
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(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 INDUSTRIAL ELECTRICAL SYSTEMS

(OE-II: Common to all branches, except EEE)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

	Q.N	o Question	Marks	со	BL
	Q.1	i. Write any two differences between MCCB and ELCB?	1M	1	1
		ii. Define fuse and fuse element.	1M	1	1
		iii. What are the advantages of earthing system?	1M	2	1
		iv Sketch the single diagram for a single phase installation	1M	2	1
		v. What is meant by depreciation?	1M	3	1
		vi What is lamp efficiency?	1M	3	1
		vii. Define depreciation factor.	1M	4	1
		viii. Define power factor.	1M	4	1
		ix. List different types of batteries available for UPS.	1M	5	1
_		x. What is the need of SCADA system in distribution automation?	1M	5	1
	Q.2(A)	Write a short note on types of cables and factors affecting the electrical wiring system.	10M	1	2
		OR			
	Q.2(B)	Explain the Electrical safety rules and Electrical Safety precautions.	10M	1	2
(Q.3(A)	Explain briefly about different types of residential and commercial	10M	2	2
		wiring systems.			
,	∩ 2/p\	OR	4004	2	2
,	Q.3(B)	Explain with the help of single line diagram the installation of three-	10M	2	2
5000		phase four-wire distribution for single and three-phase load having a common main switch fuse.			
(Q.4(A)	With the help of neat sketch, explain the construction and operation of	10M	3	2
		Incandescent lamp.			
,	2 4/D)	OR			
- (Q.4(B)	Explain the method of Light Calculation for Flood Lighting.	10M	3	2
(Q.5(A)	What is an industrial substation and with the help of a neat sketch?	10M	4	2
		explain outdoor substation.			
		OR			
(Q.5(B)		10M	4	2
		synchronous motor with the help of neat diagram.			
(Q.6(A)	Explain SCADA system for distribution automation.	10M	5	2
		OR			
(Q.6(B)	Write a short note on i) PLC based control system design	10M	5	2
		ii) Panel Metering.			
		*** = 1 = 1 = 1 = 1 = 1 = 1 = 1 = 1 = 1			

Hall Ticket No:					ì	Question Paper Code: 20ME30

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 MATERIAL SCIENCE FOR ENGINEERS

(Mechanical Engineering)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	CO	BL
Q.1	i. Define a material?	1 M	1	1
	ii. Write the classifications of structural materials?	1M	1	1
	iii. Define Fick's Law of diffusion?	1M	2	1
	iv. What is a vacancy and interstitial defect?	1M	2	1
	v. What is Electrical Conductivity?	1M	3	2
	vi What is the electron mobility?	1 M	3	1
	vii. Write the examples of paramagnetic materials?	1 M	4	2
	viii. What is called superconductivity?	1M	4	1
	ix. What are the components of photonics?	1M	5	2
	x. Write the full form of LASER?	1M	5	1
Q.2(A)	Explain the following	10M	1	2
	i) FCC ii) BCC iii) HCP iv) SC			
C ((P)	OR			
Q.2(B)	Explain the general principle of MILLER INDICES procedure with	10M	1	2
0.2(4)	example?	1015		
Q.3(A)	Write the factors affecting diffusion?	10M	2	2
	OR			
Q.3(B)	Briefly explain the most common mechanisms for diffusion?	10M	2	2
Q.4(A)	Explain about Ferroelectric Materials and Piezoelectric Materials?	10M	3	2
Q. 1(21)	Explain about refroelectife materials and riezoelectife materials?	10101	3	2
0.47	OR			
Q.4(B)	Explain briefly about Intrinsic and Extrinsic Semi conduction?	10M	3	2
Q.5(A)		10M	4	2
C ()	Differentiate the Diamagnetism and Paramagnetism?	10111	,	24
0.5(D)	OR	4075		_
Q.5(B)	Write the differences between Ferromagnetism and Ferrimagnetism.	10M	4	2
Q.6(A)	Explain about LED and OLED?	10M	5	2
- \ /	OR		Ü	_
Q.6(B)	Explain any one type of Photon absorption Devices with neat sketch?	101/	_	0
ردرای)	Explain any one type of Filoton absorption Devices with near sketch?	10M	5	2

Hall Ticket No:						Question Paper Code: 20CSE302
						Question raper code. 2005E502

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 MULTIMEDIA TECHNOLOGIES

(Common to All)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

 Q.1 i. What are the primary elements of multimedia? ii. Name two common applications of multimedia. iii. Name a common format used for compressing video files. iv. Which audio compression format is known for preserving sound quality at a reduced file size? v. What type of sensor is most commonly found in consumer digital cameras: CCD or CMOS? vi How is digital voice integrated into multimedia applications? vii. Describe one key feature of Media on Demand services. viii. What is ITV, and how does it differ from traditional television broadcasting? ix. What is the purpose of validation in the digital forensics process? x. How does steganography differ from digital watermarking? Q.2(A) Critically evaluate the standards for multimedia data interfaces. OR Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia. OR Q.3(B) Analyze the role of the MIDI file format in music production and 	1 M 1 M 1 M 1 M 1 M 1 M 1 M 1 M 1 M	1 1 2 2 3 3 4 4	1 1 1 1 1 1 1 1
iii. Name a common format used for compressing video files. iv. Which audio compression format is known for preserving sound quality at a reduced file size? v. What type of sensor is most commonly found in consumer digital cameras: CCD or CMOS? vi How is digital voice integrated into multimedia applications? vii. Describe one key feature of Media on Demand services. viii. What is ITV, and how does it differ from traditional television broadcasting? ix. What is the purpose of validation in the digital forensics process? x. How does steganography differ from digital watermarking? Q.2(A) Critically evaluate the standards for multimedia data interfaces. OR Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia.	1 M 1 M 1 M 1 M 1 M 1 M 1 M	2 2 3 3 4 4	1 1 1 1 1
iv. Which audio compression format is known for preserving sound quality at a reduced file size? v. What type of sensor is most commonly found in consumer digital cameras: CCD or CMOS? vi How is digital voice integrated into multimedia applications? vii. Describe one key feature of Media on Demand services. viii. What is ITV, and how does it differ from traditional television broadcasting? ix. What is the purpose of validation in the digital forensics process? x. How does steganography differ from digital watermarking? Q.2(A) Critically evaluate the standards for multimedia data interfaces. OR Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia.	1 M 1 M 1 M 1 M 1 M 1 M 1 M	2 3 3 4 4	1 1 1 1
quality at a reduced file size? v. What type of sensor is most commonly found in consumer digital cameras: CCD or CMOS? vi How is digital voice integrated into multimedia applications? vii. Describe one key feature of Media on Demand services. viii. What is ITV, and how does it differ from traditional television broadcasting? ix. What is the purpose of validation in the digital forensics process? x. How does steganography differ from digital watermarking? Q.2(A) Critically evaluate the standards for multimedia data interfaces. OR Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia.	1M 1M 1M 1M	3 3 4 4	1 1 1
vi How is digital voice integrated into multimedia applications? vii. Describe one key feature of Media on Demand services. viii. What is ITV, and how does it differ from traditional television broadcasting? ix. What is the purpose of validation in the digital forensics process? x. How does steganography differ from digital watermarking? Q.2(A) Critically evaluate the standards for multimedia data interfaces. OR Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia.	1 M 1 M 1 M 1 M 1 M	3 4 4	1
vii. Describe one key feature of Media on Demand services. viii. What is ITV, and how does it differ from traditional television broadcasting? ix. What is the purpose of validation in the digital forensics process? x. How does steganography differ from digital watermarking? Q.2(A) Critically evaluate the standards for multimedia data interfaces. OR Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia. OR	1 M 1 M 1 M 1 M	4	1
vii. Describe one key feature of Media on Demand services. viii. What is ITV, and how does it differ from traditional television broadcasting? ix. What is the purpose of validation in the digital forensics process? x. How does steganography differ from digital watermarking? Q.2(A) Critically evaluate the standards for multimedia data interfaces. OR Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia. OR	1 M 1 M 1 M	4	
broadcasting? ix. What is the purpose of validation in the digital forensics process? x. How does steganography differ from digital watermarking? Q.2(A) Critically evaluate the standards for multimedia data interfaces. OR Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia. OR	1 M 1 M		1
x. How does steganography differ from digital watermarking? Q.2(A) Critically evaluate the standards for multimedia data interfaces. OR Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia. OR	1M		
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Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia. OR OR		5	1
Q.2(B) Explore the structure and functionality of multimedia databases. Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia. OR	10M	1	5
Q.3(A) Explain the Resource Interchange File Format (RIFF) and its importance in multimedia. OR			
in multimedia.	10M	1	4
	10M	2	2
Q.3(B) Analyze the role of the MIDI file format in music production and			
multimedia presentations.	10M	2	4
Q.4(A) Explain video motion analysis and its applications in different fields.	10M	3	2
OR			
Q.4(B) Compare and contrast the advantages and disadvantages of various digital camera formats, including DSLRs, mirrorless, and compact cameras.	10M	3	2
Q.5(A) Analyze different broadcast schemes for Video on Demand (VoD) implications for network traffic and user experience.	10M	4	4
Q.5(B) Explore the challenges of transmitting multimedia over wireless networks and strategies to overcome them.	10M	4	2
Q.6(A) Analyze the steps involved in the forensic analysis of digital multimedia content.	10M	5	4
Q.6(B) Evaluate methods used for the validation and verification of findings in digital multimedia forensics.			5

Hall Ticket No: Question Paper Code: 20MA

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January- 2025 ADVANCED NUMERICAL METHODS (OE)

(Common to All)

Time: 3Hrs

Max Marks: 60

Q.1	i. What are the kinds of errors in Numerical procedures	Marks	CO	\mathbf{BL}
	are are annual or errors in numerical procedures	1M	1	1
	ii. Write the condition for the convergence of Newton's method	1M	1	1
	iii, Explain the process of LU decomposition method	1 M	2	1
	iv. [5 –9 6]	1M	2	3
	iv. Evaluate 1- and ∞ - norms of the matrix $A = \begin{bmatrix} 5 & -9 & 6 \\ 2 & -7 & 4 \\ 1 & 5 & 8 \end{bmatrix}$			
	v. Write the formula for inverse interpolation of the polynomial with <i>x</i> - values unevenly spaced.	1 M	3	1
	vi Define Simpson's 3/8 rule.	1 M	3	1
	vii. Define the fourth order Runge-Kutta method formula	1 M	4	1
	viii, Explain initial value and boundary value problems	1 M	4	2
	ix. Write different types of partial differential equations.	1M	5	1
	x. Write the form of vibrating spring in partial differential equation.	1M	5	1
Q.2(A)	Find a root of $f(x) = 4x^3 - 1 - \exp\left(\frac{x^2}{2}\right)$ with Newton's method	10M	1	3
O 0(B)	OR	1035		
Q.2(B)	Find a root of $f(x) = x^2 + e^x - 5$ by Regula-falsi method	10M	1	3
Q.3(A)	Solve the system $2.51x + 1.48y + 4.53z = 0.05$,	10M	2	3
	1.48x + 0.93y - 1.30z = 1.03, $2.68x + 3.04y - 1.48z = -0.53$ by using Gaussian elimination.			
	OR			
Q.3(B)	Solve the system by LU Decomposition method $2x_1 + 3x_2 + x_3 = 9$,	10M	2	3
	$x_1 + 2x_2 + 3x_3 = 6$, $3x_1 + x_2 + 2x_3 = 8$			
Q.4(A)	Find $y(2)$ from the following data using Lagrange's formula	10M	3	3
	x 0 1 3 4 5 y 0 1 81 256 625 OR			
Q.4(B)	Evaluate $\int_{0.2}^{2.6} e^{-x^2} dx$ with the proper number of sub intervals by using	10M	3	3
	a) Simpson's $\frac{1}{3}$ rule and b) Simpson's $\frac{3}{8}$ rule			
Q.5(A)	Solve $y' = \sin x + y$, $y(0) = 2$ by the modified Euler method to get y	10M	4	3

Q.5(B) Determine the value of y by the fourth order Runge-Kutta method when 10M 4 3 x=1.2 given that y(1)=0, $\frac{dy}{dx}=x^2+y^2$ and h=0.1Q.6(A) Solve the heat equation problem $\frac{\partial u}{\partial t}=\frac{\partial^2 u}{\partial x^2}$ subject to the conditions u(x,0)=0 and u(0,t)=0; u(1,t)=t, find the value of $u(\frac{1}{2},\frac{1}{8})$ taking h=0.25 and l=0.125.

OR

Q.6(B) Solve the equation $u_{tt} = u_{xx}$ subject to the following conditions 10M 5 $u(0,t) = 0, \ u(1,t) = 0, \ t > 0 \text{ and } \frac{\partial u}{\partial t}(x,0) = 0, \ u(x,0) = \sin^3(\pi x),$ $0 \le x \le 1 \text{ with } h = 0.25 \text{ and } l = 0.2.$

Hall Ticket No:						Question Paper Code: 20CE4M10

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 SAFETY IN CONSTRUCTION (MOOC)

(Civil Engineering)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	CO	BL
Q.1	i. What is the primary goal of an accident investigation?	1 M	1	1
	ii. Name one key consideration for effective fire safety management.	1 M	1	1
	iii. How does the hierarchy of controls prioritize risk mitigation strategies?	1 M	2	1
	iv. What is the purpose of a job hazard analysis?	1 M	2	1
	v. What is the penalty for violating safety regulations?	1 M	3	1
	vi What are the steps involved in performing a risk assessment?	1M	3	1
	vii. How can regular employee training contribute to improved safety outcomes?	1 M	4	1
	viii. Identify one common ergonomic hazard found in office environments.	1 M	4	1
	ix. What role does PPE play in minimizing exposure to hazardous substances?	1 M	5	1
	x. What are the key considerations for fire safety?	1 M	5	1
Q.2(A)	What are the key components of OSHA regulations that contribute to maintaining a safe working environment?	10M	1	2
	OR			
Q.2(B)	Discuss two theories of accident causation and provide examples to support your explanation.	10M	1	2
Q.3(A)	How do emergency action plans contribute to fire safety in the workplace?	10M	2	2
	OR			
Q.3(B)	What are the common causes of workplace fires, and how can they be prevented?	10M	2	2
Q.4(A)	In what ways can effective communication enhance compliance with OSHA regulations?	10M	3	3
	OR			
Q.4(B)	Discuss the importance of conducting job hazard analysis in construction and explain the steps involved in this process.	10M	3	2
Q.5(A)	Describe the process of accident investigation and explain how it preventing future accidents.	10M	4	2
	OR			
Q.5(B)	What role do regular safety audits play in identifying potential fire hazards and ensuring compliance with fire safety regulations?	10M	4	3
Q.6(A)	Describe the fire hazards typically encountered in construction sites	10M	5	2
£ · = (* *)	and discuss the preventive measures to ensure fire safety. OR	1 0 1 1 1	J	2
Q.6(B)	Describe the key components of a safety culture and discuss its significance in promoting a safe work environment. *** END***	10M	5	2

Hall Ticket No:						Question Paper Code: 20CE4M12

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 AIR POLLUTION AND CONTROL (MOOC)

(Civil Engineering)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	СО	BL
Q.1	i. Define Air Pollution?	1M	1	1
	ii. Enlist the Short-term health effects caused by Air Pollution?	1 M	1	1
	iii. Define Acid rain?	1M	2	1
	iv. Carboxy-Hemoglobin caused by?	1M	2	1
	v. What are the Source of Air pollution?	1M	3	1
	vi What is $P.M_{2.5}$?	1 M	3	1
	vii. Enlist the primary pollutants?	1 M	4	1
	viii. Write down the example for Aerial Sources of Air Pollution?	1 M	4	1
	ix. What is AQI?	1 M	5	1
	x. What is Plume?	1 M	5	1
Q.2(A)	What is Air Pollution? Explain the Causes and Control measures of Air Pollution?	10M	1	2
	OR			
Q.2(B)	Explain about the Common air pollutants which affecting human health.	10M	1	2
Q.3(A)	What is Greenhouse effect? Explain the Causes and Effects of Greenhouse effect?	10M	2	2
	OR			
Q.3(B)	Explain about different types of Plume behavior?	10M	2	2
Q.4(A)	What are the different types of Sources of air pollution? Explain it in detail?	10M	3	2
	OR			
Q.4(B)	What are the Major Indoor air pollution? How it effects the human health.	10M	3	2
Q.5(A)	Explain about any two control measures of gases matter.	10M	4	2
	OR			
Q.5(B)	Explain about any two control measures of particulates matter?	10M	4	2
Q.6(A)	What are the Materials and Method used solve the indoor air pollution problem. Explain it in detail?	10M	5	2
	OR			
Q.6(B)	Write down about Air pollution Impacts on (i) atmosphere (ii) climate (iii) soil	10M	5	2

Hall Ticket No:						Question Paper Code: 20CE4M11

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 PLASTIC WASTE MANAGEMENT (MOOC)

(Civil Engineering)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Marks	CO	BL
Q.1	i. What is Plastic waste means?	1 M	1	1
	ii. What is Thermoplastic?	1M	1	1
	iii. Define Compostable Plastic?	1 M	2	1
	iv. Which state in India is now completely Plastic free?	1 M	2	1
	v. In which year Plastic rules were revised?	1 M	3	1
	vi Define Rigid Plastic?	1 M	3	1
	vii. PET Stands for?	1 M	4	1
	viii. What is the key objective of the Plastic Waste Management Rules 2016 in India?	1M	4	1
	ix. Which type of plastic is most widely recycled?	1M	5	1
	x. What is the effect of micro plastics on human health?	1 M	5	1
Q.2(A)	What is Plastic? Explain about different types of Plastic in detail?	10M	1	2
	OR			
Q.2(B)	Explain about different types of Manufacturing Process of Plastic?	10M	1	2
Q.3(A)	What are the Sources of plastic waste? Explain it in detail?	10M	2	2
	OR			
Q.3(B)	Discuss the Plastic Waste Management Rules 2016 (India), including their objectives and challenges.	10M	2	2
Q.4(A)	What are the environmental impacts of plastic waste on land and water ecosystems?	10M	3	2
	OR			
Q.4(B)	Write down about Plastic Waste Impacts on Human Health and Environment	10M	3	2
Q.5(A)	Discuss the challenges and benefits of using plastic waste in road	10M	4	2
	construction.			
	OR			
Q.5(B)	What are the potential greener alternatives to plastics, and what are their benefits?	10M	4	2
Q.6(A)	Discuss the role of the public in plastic waste management. What are some effective awareness campaigns?	10M	5	2
	OR			
Q.6(B)	How can plastics contribute to a circular economy? Discuss the processes involved.	10M	5	2
	*** FND***			

Hall Ticket No: Question Paper Code: 201	EEE4M060
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B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 NON-CONVENTIONAL ENERGY RESOURCES (MOOC)

(Electrical & Electronics Engineering)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.No	Question	Marks	CO	BL
Q.1	i. Why does the presence of carbon dioxide gas in the atmosphere affect the global temperature?	1M	1	2
	ii. State the significance of GDP in a nation.	1M	1	1
	iii. A p-n junction semiconductor material is kept in the sunlight for some time. What will be the biasing condition of this junction?	1M	2	2
	iv Which region of a p-n junction is critical to the capture of solar energy by preventing recombination?	1 M	2	2
	v. What is Betz limit?	1 M	3	1
	vi Define HAWT and VAWT	1M	3	1
	vii. What is the disadvantage of dendrite growth in Lithium battery?	1 M	4	2
	viii. State the significance of OTEC plant	1 M	4	1
	ix. Define regenerative breaking?	1M	5	1
	x. Write down the differences between capacitor and super capacitor.	1 M	5	1
Q.2(A)	Describe the different kinds of energy sources available in India and discuss the energy consumption pattern.	10M	1	2
Q.2(B)	Classify the different types of energy sources. Write about the worldwide consumption pattern of these sources.	10M	1	3
Q.3(A)	Write solar PV cell principal of operation and explain the IV characteristics, I_{sc} , V_{oc} and FF and their relations. OR	10M	2	2
Q.3(B)	Describe in detail about the components of solar thermal energy systems in context with power generation.	10M	2	1
Q.4(A)	Describe in detail about the relation between wind speed and power. With the help of equations, derive the power extracted from the wind. OR	10M	3	3
Q.4(B)	Discuss the working principle of horizontal axis wind turbine and vertical axis wind turbine in detail.	10M	3	2
Q.5(A)	Mention the various sources of biomass energy. What are the various crop residues used for biomass.	10M	4	2
Q.5(B)	Explain in detail about the geothermal power plant with neat diagram.	10M	4	2
Q.6(A)	Briefly explain the concepts of super-capacitors in terms of charging & discharging properties and energy storage. OR	10M	5	2
Q.6(B)	Briefly explain the concept of flywheel energy storage system.	10M	5	3

Hall Ticket No:						Question Paper Code: 20ME4M09

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 ITRODUCTION TO MACHINING AND MACHINING FLUIDS (MOOC)

(Mechanical Engineering)

Time: 3Hrs

Max Marks: 60

Attempt all the questions. All parts of the question must be answered in one place only.

All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer either A or B only

Q.1 i. What is the difference between top-down and bottom-up approaches in manufacturing? ii. How is chip thickness measured in machining? iii. What are the different types of lubrication used in machining? iii. What are the health hazards associated with cutting fluid in machining? v. What are the health hazards associated with cutting fluid in machining? vi What factors affect tool life in machining? vii. What is the difference between single-point and multi-point cutting tools? viii. What is the difference between single-point and multi-point cutting tools? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. What are advanced materials? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing the manufacturing industry. provide examples of various machining in the manufacturing industry. Provide examples of various machining processes and their applications. OR Q.2(A) Discuss the various cutting forces acting on a cutting tool during machining. Explain how these forces are measured and their impact on tool wear and surface finish. OR Q.3(B) Elaborate on the different types of lubrication used in machining, including 10M 2 2 2 in machining. Explain how friction and wear affect the cutting process. OR Q.4(A) Discuss the various mechanisms of tool wear in machining, including their causes and effects on tool performance. OR Q.5(B) Discuss the various abrasive machining fluids in machining, including flow 10M	Q.No	Question	Marks	CO	BL
ii. How is chip thickness measured in machining? iii. What are the different types of lubrication used in machining? iv. How is surface roughness measured and controlled in machining? iv. What are the health hazards associated with cutting fluid the missions? vi. What is the health hazards associated with cutting fluid the missions? vii. What is the difference between single-point and multi-point cutting the tools? viii. What is the difference between single-point and multi-point cutting the tools? viii. How does superfinishing differ from other finishing processes? ix. What are advanced materials? x. What are the challenges associated with machining advanced the challenges associated with machining advanced to the challenges associated with machining in the manufacturing industry. Q.2(A) Discuss the importance of machining in the manufacturing industry. OR Q.2(B) Discuss the various cutting forces acting on a cutting tool during machining. Explain how these forces are measured and their impact on tool wear and surface finish. Q.3(A) Discuss the role of tribology in understanding the tool-workpiece interface in machining. Explain how friction and wear affect the cutting process. OR Q.4(A) Discuss the various mechanisms of tool wear in machining, including their causes and effects on tool performance. OR Q.4(B) Discuss the various functions of cutting fluids in machining, including their causes and effects on tool performance. OR Q.5(B) Discuss the various abrasive machining processes, including grinding, low 4 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	Q.1	The state of the s			
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iv. How is surface roughness measured and controlled in machining? v. What are the health hazards associated with cutting fluid v. What are the health hazards associated with cutting fluid vii. What is the difference between single-point and multi-point cutting tools? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? IM 4 2 ix. What are advanced materials? NA 5 1 X. What are the challenges associated with machining advanced IM 5 1 X. What are the challenges associated with machining advanced IM 5 2 Provide examples of various machining in the manufacturing industry. OR Q.2(B) Discuss the importance of machining in the manufacturing industry. OR Q.3(A) Discuss the various cutting forces acting on a cutting tool during machining. Explain how these forces are measured and their impact on tool wear and surface finish. Q.3(A) Discuss the role of tribology in understanding the tool-workpiece interface in machining. Explain how friction and wear affect the cutting process. OR Q.3(B) Elaborate on the different types of lubrication used in machining, including their causes and effects on tool performance. OR Q.4(B) Discuss the various mechanisms of tool wear in machining, including their causes and effects on tool performance. OR Q.5(A) Explain the principle of milling and drilling process. OR Q.5(B) Discuss the various abrasive machining processes, including grinding, loM 4 2 lapping, honing, and superfinishing. Q.6(A) Explain the principles of hard machining and its applications. Discuss the cha			1 M	1	1
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vii. What is the difference between single-point and multi-point cutting tools? viii. How does superfinishing differ from other finishing processes? viii. How does superfinishing differ from other finishing processes? ix. What are advanced materials? x. What are the challenges associated with machining advanced materials? Q.2(A) Discuss the importance of machining in the manufacturing industry. Provide examples of various machining processes and their applications. OR Q.2(B) Discuss the various cutting forces acting on a cutting tool during machining. Explain how these forces are measured and their impact on tool wear and surface finish. Q.3(A) Discuss the role of tribology in understanding the tool-workpiece interface in machining. Explain how friction and wear affect the cutting process. OR Q.3(B) Elaborate on the different types of lubrication used in machining, including their causes and effects on tool performance. OR Q.4(A) Discuss the various mechanisms of tool wear in machining, including their causes and effects on tool performance. OR Q.4(B) Discuss the various functions of cutting fluids in machining, including tooling, lubrication, chip removal, and cleaning. Q.5(A) Explain the principle of milling and drilling processes, including grinding, lapping, honing, and superfinishing. Q.5(B) Discuss the various abrasive machining and its applications. Discuss the challenges and advantages of using hard machining techniques.			1 M	3	1
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Q.3(B) Elaborate on the different types of lubrication used in machining, including their advantages and disadvantages. Q.4(A) Discuss the various mechanisms of tool wear in machining, including their causes and effects on tool performance. OR Q.4(B) Discuss the various functions of cutting fluids in machining, including cooling, lubrication, chip removal, and cleaning. Q.5(A) Explain the principle of milling and drilling process. OR Q.5(B) Discuss the various abrasive machining processes, including grinding, lapping, honing, and superfinishing. Q.6(A) Explain the principles of hard machining and its applications. Discuss the challenges and advantages of using hard machining techniques. OR	Q.3(A)	in machining. Explain how friction and wear affect the cutting process.	10M	2	2
causes and effects on tool performance. OR Q.4(B) Discuss the various functions of cutting fluids in machining, including 10M 3 1 cooling, lubrication, chip removal, and cleaning. Q.5(A) Explain the principle of milling and drilling process. OR Q.5(B) Discuss the various abrasive machining processes, including grinding, 10M 4 2 lapping, honing, and superfinishing. Q.6(A) Explain the principles of hard machining and its applications. Discuss the challenges and advantages of using hard machining techniques. OR	Q.3(B)	Elaborate on the different types of lubrication used in machining, including	10M	2	2
Q.4(B) Discuss the various functions of cutting fluids in machining, including 10M 3 1 cooling, lubrication, chip removal, and cleaning. Q.5(A) Explain the principle of milling and drilling process. OR Q.5(B) Discuss the various abrasive machining processes, including grinding, 10M 4 2 lapping, honing, and superfinishing. Q.6(A) Explain the principles of hard machining and its applications. Discuss the challenges and advantages of using hard machining techniques. OR	Q.4(A)	causes and effects on tool performance.	10M	3	1
OR Q.5(B) Discuss the various abrasive machining processes, including grinding, 10M 4 2 lapping, honing, and superfinishing. Q.6(A) Explain the principles of hard machining and its applications. Discuss the 10M 5 2 challenges and advantages of using hard machining techniques. OR	Q.4(B)	Discuss the various functions of cutting fluids in machining, including	10M	3	1
Q.5(B) Discuss the various abrasive machining processes, including grinding, 10M 4 2 lapping, honing, and superfinishing. Q.6(A) Explain the principles of hard machining and its applications. Discuss the 10M 5 2 challenges and advantages of using hard machining techniques. OR	Q.5(A)	Explain the principle of milling and drilling process.	10M	4	2
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challenges and advantages of using hard machining techniques. OR	Q.5(B)	Discuss the various abrasive machining processes, including grinding, lapping, honing, and superfinishing.	10M	4	2
Q.6(B) Discuss the advantages and disadvantages of using high-speed machining. 10M 5 2	Q.6(A)	Explain the principles of hard machining and its applications. Discuss the challenges and advantages of using hard machining techniques.	10M	5	2
	Q.6(B)	Discuss the advantages and disadvantages of using high-speed machining.	10M	5	2

Hall Ticket No:						Question Paper Code: 20ECE4M03
						Question raper code. 2010141003

(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 COMPUTER NETWORKS AND INTERNET PROTOCOL (MOOC)

(ECE)

Time: 3Hrs Max Marks: 60

Q.I	No Question	Marks	СО	BL
Q.1	i. Who defines the Internet architecture?	1M	1	1
	ii. Define the Internet Protocol (IP).	1M	1	1
	iii. What is the purpose of DNS in computer networks.	1M	2	1
	iv What is congestion avoidance?	1M	2	1
	v. Name two common Transport Layer protocols.	1M	3	1
	vi What is the role of router in network layer?	1M	3	1
	vii. Expand DHCP.	1M	4	1
	viii. Define subnetting in the Network Layer.	1M	4	2
	ix. What is the full form of CSMA/CD?	1M	5	1
	x. Define the term "framing" in the Data Link Layer.	1M	5	1
Q.2(A)	Explain the principles of packet switching, emphasizing its dedicated	10M	1	2
	and continuous communication paths.			
(-)	OR			
Q.2(B)	Discuss specific functions and responsibilities of each layer in the	10M	1	2
	TCP/IP protocol stack.			
Q.3(A)	Discuss the following application layer services:	10M	2	2
	i. Email ii. DNS			
0.0(5)	OR			
Q.3(B)	Discuss the following application layer services:	10M	2	1
	i. HTTP ii. FTP			
Q.4(A)	Explain the concept of flow control in the transport layer. How this	10M	3	2
	mechanism contributes to the efficient and reliable transfer of data			
	across a network.			
0.4/5\	OR			
Q.4(B)	Explain the concept of sliding window protocols in the context of data	10M	3	2
	communication.		-	
Q.5(A)	Differentiate between IPv4 and IPv6 addressing schemes. What are the	10M	4	4
	main reasons for transitioning from IPv4 to IPv6?			
	OR			
Q.5(B)	Analyze the significance of scheduling in Queuing and Congestion	10M	4	4
	Avoidance.			
Q.6(A)	Explain the following:	10M	5	2
	i. Logical Link Control ii. Medium Access Control			
	OR			
Q.6(B)	Explain time division multiplexing with neat block diagram.	10M	5	2
	*** END***			

(UGC-AUTONOMOUS)

B.Tech. III Year II Semester (R20) Supplementary End Semester Examinations – January 2025 COMMUNICATION NETWORKS (MOOC)

(Common to EEE & ECE)

Time: 3Hrs	Max Marks: 60
Attempt all the questions. All parts of the question must be ar	nswered in one place only.
All parts of Q.no 1 are compulsory. In Q.no 2 to 6 answer	either Part-A or B only

Q. No	Question	Marks	СО	BL
	i. What is space switching?	1M	1	1
	ii. What is the difference between Circuit Switching & Packet	1M	1	2
	Switching?			
	iii. Mention the advantage and disadvantage of slotted ALOHA	1M	2	1
	iv. What is PON?	1M	2	1
Q.1	v. Define RARP.	1M	3	1
	vi. What is ARP?	1M	3	2
	vii. What is memoryless system ?	1M	4	1
	viii. What is DTMC?	1M	4	1
	ix. Define cognitive network.	1M	5	1
,	x. What is network Slicing?	1M	5	1
Q.2(A)	Explain 4x4 STS switching in detail.	10M	1	1
	OR			
Q.2(B)	Explain Synchronization in switching in detail.	10M	1	1
Q.3(A)	Why CSMA/CD is required for Wired communication? Explain CSMA/CD	10M	2	1
	Computing Detection in detail with neat diagram.			
	OR			
Q.3(B)	Explain Slotted ALOHA protocol in detail.	10M	2	1
Q.4(A)	Explain Distance Vector Routing Protocol with example.	10M	3	1
Q.4(B)	Explain TCP Flow control mechanism in detail.	10M	3	1
Q.5(A)	State and prove the Little's Theorem.	10M	4	2
(٨)		TOIVI	4	2
	OR			
Q.5(B)	Explain in detail about DTMC.	10M	4	1
Q.6(A)	What is Cognitive Network & explain in detailed about Software-Defined	10M	5	1
	Networking (SDN)?			
	OR			
Q.6(B)	Write shot note on NAT and NFV.	10M	5	1
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Hall Ticket No:						Question Paper Code: 20CSE4M08
						/20CAI4M08

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 CLOUD COMPUTING AND DISTRIBUTED SYSTEMS (MOOC)

(Common to CSE and, CSE-AI)

Time: 3Hrs

Max Marks: 60

Q.No		Question	Marks	СО	BL
Q.1	i.	What are the three service models of cloud computing?	1M	1	1
	ii.	Define virtualization in cloud computing.	1 M	1	1
	iii.	What is server virtualization?	1M	2	1
	iv.	Define Software-Defined Network (SDN).	1M	2	1
	v.	Define the term "ring structure" in leader election.	1M	3	1
	vi	Name two leader election algorithms.	1M	3	1
	vii.	Define Chandy-Lamport snapshot algorithm.	1M	4	1
	viii.	Mention one type of failure in distributed systems.	1M	4	1
	ix.	Define HBase.	1 M	5	1
	X.	Name one feature of Apache Kafka.	1M	5	1
Q.2(A)	Discu	ss the challenges of cloud computing.	10M	1	2
		OR			
Q.2(B)	Expla	in hotspot mitigation in virtual machine migration with an example.	10M	1	2
Q.3(A)	Descr	ibe the architecture of geo-distributed cloud data centers.	10M	2	2
		OR			
Q.3(B)	What	are the challenges in managing cloud data centers?	10M	2	2
Q.4(A)	Expla exam	in the working of the Ring Leader Election Algorithm with an ple.	10M	3	2
		OR			
Q.4(B)	Expla	in the architecture and features of Zookeeper.	10M	3	2
Q.5(A)	Expla	in logical and physical clocks with examples.	10M	4	2
		OR			
Q.5(B)	Descr	ibe the Paxos algorithm for consensus in cloud computing.	10M	4	2
	Expla	in the design and applications of key-value stores.	10M	5	2
Q.6(A)	Dapia			_	
Q.6(A)	Биріц	OR			

Hall Ticket No:						Question Paper Code: 20CST4M04 /20CSD4M04 / 20CSC4M04
						/ 20C3D4MU4 / 20C3C4MU4

B. Tech III Year II Semester (R20) Supplementary End Semester Examinations, January - 2025 PRIVACY AND SECURITY IN ONLINE SOCIAL MEDIA (MOOC)

(Common to CST, CSE-DS and CSE-CS)

Time: 3Hrs

Max Marks: 60

Q.No	Question	Mark	s CO	BL
Q.1	i. What does Velocity specify in 5 V's of social media?	1M	1	1
	ii. Which network is considered as the regional language micro be website?	ologging 1M	1	1
	iii. Which features perform better to distinguish fake and leg tweets?	gitimate 1M	2	1
	iv Tweet about, "Floods in McDonalds at Virginia Beach" is reward which misinformation news spreads?	lated to 1M	2	1
	v. Name the pair of social platforms that are adopted by different departments to engage with people.		3	2
	vi An adjacency matrix and XML file format are prefera representing what kind of data?		3	1
	vii. Which Centrality measure is appropriate for finding the most person in the friendship network?	popular 1M	4	1
	viii. What is the legit way to identify the popularity of a web page?	1M	4	5
	ix. Give an example for location based social networks.	1M	5	2
	x. What is the term used for generating the usernames and mone	tizing? 1M	5	1
Q.2(A)	Discuss the different types of social media in an online network. OR	10M	1	2
Q.2(B)	Explain 5 V's of online social media.	10M	1	2
Q.3(A)	Elaborate with an example about the location based social network.	10M	2	2
	OR			
Q.3(B)	Describe the terminologies of Twitter.	10M	2	1
Q.4(A)	How we can identify fake account in Online Social Media Platform. lin detail.	Explain 10M	3	3
	OR			
Q.4(B)	Discuss the different types of phishing Attacks in an online network.	10M	3	2
Q.5(A)	With suitable graph diagram, explain Network Analysis of Fake Accou OR	ants. 5M	4	2
Q.5(B)	Discuss in detail about Westin's 3 categories.	10M	4	2
Q.6(A)	Elaborate the different Privacy and security issues related to location networks.	based 10M	5	2
	OR			
Q.6(B)	Discuss about various methods available for Analyzing Fake Contessocial media platforms.	ent on 10M	5	2
	*** FND***			